LM940
HW Design Guide

1VV0301352 Rev. 15 2020-05-11

TELIT
TECHNICAL
DOCUMENTATION

SPECIFICATIONS ARE SUBJECT TO CHANGE WITHOUT NOTICE

NOTICE

While reasonable efforts have been made to assure the accuracy of this document, Telit assumes no liability resulting from any inaccuracies or omissions in this document, or from use of the information obtained herein. The information in this document has been carefully checked and is believed to be reliable. However, no responsibility is assumed for inaccuracies or omissions. Telit reserves the right to make changes to any products described herein and reserves the right to revise this document and to make changes from time to time in content hereof with no obligation to notify any person of revisions or changes. Telit does not assume any liability arising out of the application or use of any product, software, or circuit described herein; neither does it convey license under its patent rights or the rights of others.

It is possible that this publication may contain references to, or information about Telit products (machines and programs), programming, or services that are not announced in your country. Such references or information must not be construed to mean that Telit intends to announce such Telit products, programming, or services in your country.

COPYRIGHTS

This instruction manual and the Telit products described in this instruction manual may be, include or describe copyrighted Telit material, such as computer programs stored in semiconductor memories or other media. Laws in the Italy and other countries preserve for Telit and its licensors certain exclusive rights for copyrighted material, including the exclusive right to copy, reproduce in any form, distribute and make derivative works of the copyrighted material. Accordingly, any copyrighted material of Telit and its licensors contained herein or in the Telit products described in this instruction manual may not be copied, reproduced, distributed, merged or modified in any manner without the express written permission of Telit. Furthermore, the purchase of Telit products shall not be deemed to grant either directly or by implication, estoppel, or otherwise, any license under the copyrights, patents or patent applications of Telit, as arises by operation of law in the sale of a product.

COMPUTER SOFTWARE COPYRIGHTS

The Telit and 3rd Party supplied Software (SW) products described in this instruction manual may include copyrighted Telit and other 3rd Party supplied computer programs stored in semiconductor memories or other media. Laws in the Italy and other countries preserve for Telit and other 3rd Party supplied SW certain exclusive rights for copyrighted computer programs, including the exclusive right to copy or reproduce in any form the copyrighted computer program. Accordingly, any copyrighted Telit or other 3rd Party supplied SW computer programs contained in the Telit products described in this instruction manual may not be copied (reverse engineered) or reproduced in any manner without the express written permission of Telit or the 3rd Party SW supplier. Furthermore, the purchase of Telit products shall not be deemed to grant either directly or by implication, estoppel, or otherwise, any license under the copyrights, patents or patent applications of Telit or other 3rd Party supplied SW, except for the normal non-exclusive, royalty free license to use that arises by operation of law in the sale of a product.

USAGE AND DISCLOSURE RESTRICTIONS

I. License Agreements

The software described in this document is the property of Telit and its licensors. It is furnished by express license agreement only and may be used only in accordance with the terms of such an agreement.

II. Copyrighted Materials

Software and documentation are copyrighted materials. Making unauthorized copies is prohibited by law. No part of the software or documentation may be reproduced, transmitted, transcribed, stored in a retrieval system, or translated into any language or computer language, in any form or by any means, without prior written permission of Telit

III. High Risk Materials

Components, units, or third-party products used in the product described herein are NOT fault-tolerant and are NOT designed, manufactured, or intended for use as on-line control equipment in the following hazardous environments requiring fail-safe controls: the operation of Nuclear Facilities, Aircraft Navigation or Aircraft Communication Systems, Air Traffic Control, Life Support, or Weapons Systems (High Risk Activities"). Telit and its supplier(s) specifically disclaim any expressed or implied warranty of fitness for such High Risk Activities.

IV. Trademarks

TELIT and the Stylized T Logo are registered in Trademark Office. All other product or service names are the property of their respective owners.

V. Third Party Rights

The software may include Third Party Right software. In this case you agree to comply with all terms and conditions imposed on you in respect of such separate software. In addition to Third Party Terms, the disclaimer of warranty and limitation of liability provisions in this License shall apply to the Third Party Right software.

TELIT HEREBY DISCLAIMS ANY AND ALL WARRANTIES EXPRESS OR IMPLIED FROM ANY THIRD PARTIES REGARDING ANY SEPARATE FILES, ANY THIRD PARTY MATERIALS INCLUDED IN THE SOFTWARE, ANY THIRD PARTY MATERIALS FROM WHICH THE SOFTWARE IS DERIVED (COLLECTIVELY “OTHER CODE”), AND THE USE OF ANY OR ALL THE OTHER CODE IN CONNECTION WITH THE SOFTWARE, INCLUDING (WITHOUT LIMITATION) ANY WARRANTIES OF SATISFACTORY QUALITY OR FITNESS FOR A PARTICULAR PURPOSE.

NO THIRD PARTY LICENSORS OF OTHER CODE SHALL HAVE ANY LIABILITY FOR ANY DIRECT, INDIRECT, INCIDENTAL, SPECIAL, EXEMPLARY, OR CONSEQUENTIAL DAMAGES (INCLUDING WITHOUT LIMITATION LOST PROFITS), HOWEVER CAUSED AND WHETHER MADE UNDER CONTRACT, TORT OR OTHER LEGAL THEORY, ARISING IN ANY WAY OUT OF THE USE OR DISTRIBUTION OF THE OTHER CODE OR THE EXERCISE OF ANY RIGHTS GRANTED UNDER EITHER OR BOTH THIS LICENSE AND THE LEGAL TERMS APPLICABLE TO ANY SEPARATE FILES, EVEN IF ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Applicability Table

PRODUCTS

- LM940 1.0
- LM940 2.0

Information –LM940 HW Versions 1.0 and 2.0 only differ in the pin-out. Both variants support the very same features and functions.

Please refert to the section 3. PINS ALLOCATION for more details.

Contents

1. INTRODUCTION

1.1. Scope

This document introduces the Telit LM940 module and presents possible and recommended hardware solutions for developing a product based on the LM940 module. All the features and solutions detailed in this document are applicable to all LM940 variants, where “LM940” refers to the variants listed in the Applicability Table.

If a specific feature is applicable to a specific product only, it will be clearly marked.

Information – LM940 refers to all modules listed in the Applicability Table.

This document takes into account all the basic functions of a wireless module; a valid hardware solution is suggested for each function, and incorrect solutions and common errors to be avoided are pointed out.

Obviously, this document cannot embrace every hardware solution or every product that can be designed. Where the suggested hardware configurations need not be considered mandatory, the information given should be used as a guide and a starting point for properly developing a product using the Telit LM940 module.

Information – The integration of the WCDMA/HSPA+/LTE LM940 cellular module within a user application must be carried out according to the design rules described in this manual.

1.2. Audience

This document is intended for Telit customers, especially system integrators, about to implement their applications using the Telit LM940 module.

1.3. Contact Information, Support

For general contact, technical support services, technical questions and report documentation errors contact Telit Technical Support at:

- TS-EMEA@telit.com
- TS-AMERICAS@telit.com
- TS-APAC@telit.com
- TS-SRD@telit.com

Alternatively, use:

http://www.telit.com/en/products/technical-support-center/contact.php

For detailed information about where you can buy the Telit modules or for recommendations on accessories and components visit:

http://www.telit.com

To register for product news and announcements or for product questions contact Telit's Technical Support Center (TTSC).

Our aim is to make this guide as helpful as possible. Keep us informed of your comments and suggestions for improvements.

Telit appreciates feedback from the users of our information.

1.4. Text Conventions

Danger – This information MUST be followed or catastrophic equipment failure or bodily injury may occur.

Caution or Warning – Alerts the user to important points about integrating the module, if these points are not followed, the module and end user equipment may fail or malfunction.

Tip or Information – Provides advice and suggestions that may be useful when integrating the module.

All dates are in ISO 8601 format, i.e. YYYY-MM-DD.

1.5. Related Documents

- LM940 SW User Guide, 1VV0301343
- LM940 AT Commands Reference Guide, 80545ST10791A
- Generic EVB HW User Guide, 1VV0301249
- LM940 Interface Board HW User Guide, 1VV0301384
- SIM Integration Design Guide Application Note Rev10, 80000NT10001A
- Antenna Detection Application Note, 80000NT10002A

2. GENERAL PRODUCT DESCRIPTION

2.1. Overview

The aim of this document is to present possible and recommended hardware solutions useful for developing a product with the Telit LM940 Mini PCIe module.

LM940 is Telit's platform for Mini PCIe module for applications, such as M2M applications and industrial IoT device platforms, based on the following technologies:

- LTE / WCDMA networks for data communication
- Designed for industrial grade quality

In its most basic use case, LM940 can be applied as a wireless communication front-end for mobile products, offering mobile communication features to an external host CPU through its rich interfaces.

LM940 is available in hardware variants as listed in Applicability Table
The designated RF band sets per each variant are detailed in Section 2.2, Product Variants and Frequency Bands.

2.2. Product Variants and Frequency Bands

The operating frequencies in LTE & WCDMA modes conform to the 3GPP specifications.

2.2.1. RF Bands per Regional Variant

This table summarizes the LM940, showing the supported band sets and the supported band pairs and triple for carrier aggregation.

RF Bands and Carrier Aggregation

2.2.1.1. Generic Image Frequency Bands and CA Combinations

	LTE FDD	LTE TDD	HSPA+
Bands	1, 2, 3, 4, 5, 7, 8, 12, 13, 17, 20, 25, 26, 28, 29, 30, 66	38, 40, 41	1, 2, 4, 5, 8
GNSS	GPS, GLONASS, BeiDou, Galileo		
LTE 2DL carrier aggregation combinations			
2CA	CA_1A_3A, CA_1A_5A, CA_1A_7A, CA_1A_8A, CA_1A_20A, CA_1A_28A, CA_3A_3A, CA_3A_5A, CA_3A_7A, CA_3A_8A, CA_3A_20A, CA_3A_28A, CA_5A_7A, CA_5A_40A, CA_7A_7A, CA_7A_8A, CA_7A_20A, CA_7A_28A, 28A_40A, CA_40A_40A, 3C, CA_5B, CA_7B, CA_7C, CA_38C, CA_40C		
LTE 3DL carrier aggregation combinations			

	CA_1A_3A_5A, CA_1A_3A_8A, CA_1A_3A_20A, CA_1A_3A_28A, CA_1A_5A_7A, CA_1A_7A_20A, CA_1A_7A_28A, CA_3A_3A_8A, CA_3A_7A_8A, CA_3A_7A_20A, CA_3A_7A_28A, CA_1A_3C, CA_3A_7B, CA_3A_7C, CA_3C_5A, CA_3C_7A, CA_3C_20A, CA_5A_40C, CA_7B_28A, CA_7C_28A, CA_28A_40C, CA_40D

2.2.1.2. AT&T Image Frequency Bands and CA Combinations

	LTE FDD	LTE TDD	HSPA+
Bands	2, 4, 5, 12, 29, 30, 66	N/A	2, 5
LTE 2DL carrier aggregation combinations			
2CA	CA_2A_4A, CA_2A_5A, CA_2A_12A,2A_29A, CA_2A_30A, CA_2A_66A, CA_4A_5A, CA_4A_12A, CA_4A_29A, CA_4A_30A, CA_5A_30A, CA_5A_66A, CA_12A_30A, CA_12A_66A, CA_30A_29A, CA_30A_66A, CA_66A_29A, CA_2A_2A, CA_4A_4A, CA_66A_66A, CA_2C, CA_5B, CA_12B, CA_66B, CA_66C		
3CA	CA_2A_2A_5A, CA_2A_2A_12A, CA_2A_4A_5A, CA_2A_4A_12A, CA_2A_5A_30A, CA_2A_5A_66A, CA_2A_12A_30A, CA_2A_12A_66A, CA_ 2A_29A_30A, CA_4A_4A_5A, CA_4A_4A_12A, CA_4A_5A_30A,4A_12B, CA_4A_12A_30A, CA_4A_29A_30A, CA_5A_30A_66A, CA_5A_66A_66A, CA_5A_66C, CA_12A_30A_66A, CA_12A_66A_66A		

2.2.1.3. Verizon Image Frequency Bands and CA Combinations

	LTE FDD	LTE TDD	HSPA+
Bands	2, 4, 5, 13, 66	N/A	N/A
2CA	CA_2A_4A, CA_2A_5A, CA_2A_13A, CA_2A_66A, CA_4A_5A,4A_13A, CA_5A_66A, CA_13A_66A, CA_2A_2A, CA_4A_4A, CA_66A_66A, CA_5B, CA_66B, CA_66C		
3CA	2A_2A_5A, CA_2A_2A_13A, CA_2A_4A_5A, CA_2A_4A_13A, CA_2A_5A_66A, CA_2A_13A_66A, CA_4A_4A_5A, CA_4A_4A_13A, CA_5A_66A_66A, CA_13A_66A_66A, CA_66A_66C, CA_2A_66C, CA_5A_66C, CA_13A_66C		

2.2.1.4. Sprint Image Frequency Bands and CA Combinations

	LTE FDD	LTE TDD	HSPA+
Bands	2, 4, 5, 12, 25, 26	41	N/A
2CA	CA_25A_25A, CA_25A_26A, CA_26A_41A, CA_41A_41A, CA_41C		
3CA	CA_26A_41C, CA_41A_41C, CA_41D		

Refer to Chapter 13 for details information about frequencies and bands.

2.3. Target market

LM940 can be used for applications where very high bandwidth, extensive band coverage and multiple network carriers certifications in a single SKU are required, such as:

- Industrial equipment
- Internet connectivity devices (mobile reuters, access points)

2.4. Main features

The LM940 family of industrial grade cellular modules features LTE and multi-RAT module together with an on-chip powerful application processor and a rich set of interfaces.

The major functions and features are listed below.

Main Features

Function	Features

Module	• Multi-RAT cellular module for data communication
	  ○ LTE FDD/TDD Cat11(600/75 Mbps DL/UL)
	  ○ WCDMA up to DC HSPA+, Rel.9
	• Support for GPS, GLONASS, BeiDou, Galileo

Two USIM ports – dual voltage	• Support of two SIM interfaces • Class B and Class C support • Clock rates up to 4 MHz

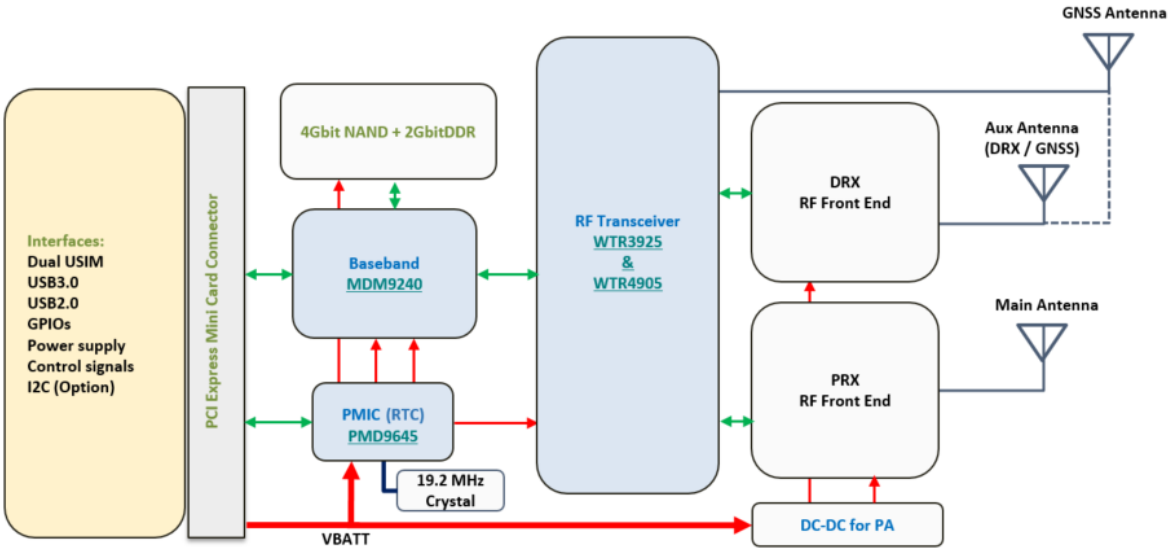
Interfaces	Rich set of interfaces, including:
	• USB2.0 / USB3.0 – USB port is typically used for:
	  ○ Flashing of firmware and module configuration
	  ○ Production testing
	  ○ Accessing the Application Processor's file system

Function	Features
	○ AT command access ○ High-speed WWAN access to external host ○ Diagnostic monitoring and debugging ○ Communication between Java application environment and an external host CPU ○ NMEA data to an external host CPU • Peripheral Ports – GPIOs
Major software features	• Advanced security features ○ Boot integrity of firmware up to customer applications ○ Embedded security • FOTA (optional) • Telit Unified AT command set
Form factor	Mini PCIe Form factor (50.95x30x2.7mm), accommodating multiple RF bands
Environment and quality requirements	The entire module is designed and qualified by Telit to satisfy environment and quality requirements for use in applications.
Single supply module	The module generates all its internal supply voltages.
RTC	Real-time clock is supported.
Operating temperature	Range -40 °C to +85 °C (conditions as defined in Section 2.10.1, Temperature Range)

2.5. Block Diagram

Below figure shows an overview of the internal architecture of the LM940 module.

LM940 Block Diagram



It includes the following sub-functions:

- Application processor, Module subsystem and Location processing with their external interfaces. These three functions are contained in a single SOC.
- RF front end
- Rich IO interfaces. Depending on which LM940 software features are enabled, some of its interfaces that are exported through multiplexing may be used internally and thus may not be usable by the application.
- PMIC with the RTC function inside

2.6. TX Output Power

Band	Power class
3G WCDMA	Class 3 (0.2W)
LTE All Bands	Class 3 (0.2W)

2.7. RX Sensitivity

Below the 3GPP measurement conditions used to define the RX sensitivity:

Technology	3GPP Compliance
4G LTE	Throughput >95% 10MHz Dual Receiver
3G WCDMA	BER <0.1% 12.2 Kbps Dual Receiver

Product	Band	Typical Rx Sensitivity (dBm) * / ** (LTE BW = 10 MHz)
LM940	LTE FDD B1	-101.5
	LTE FDD B2	-101.0
	LTE FDD B3	-101.5
	LTE FDD B4	-101.0
	LTE FDD B5	-102.5
	LTE FDD B7	-99.5
	LTE FDD B8	-102.5
	LTE FDD B12	-102.0
	LTE FDD B13	-102.0
	LTE FDD B17	-102.0
	LTE FDD B20	-102.0
	LTE FDD B25	-101.0
	LTE FDD B26	-102.0
	LTE FDD B28	-102.0
	LTE FDD B66	-101.0
	LTE TDD B38	-100.0
	LTE TDD B40	-100.0
	LTE TDD B41	-99.5
LM940	WCDMA FDD B1	-108.5
	WCDMA FDD B2	-108.5
	WCDMA FDD B4	-108.5
	WCDMA FDD B5	-109.5
	WCDMA FDD B8	-109.5

* LTE Rx Sensitivity shall be verified by using both (all) antenna ports simultaneously.

** 3.3 Voltage / Room temperature

2.8. GNSS Receiver Specifications

GNSS receiver is a Qualcomm Gen 8c device.

Parameters	Range	Notes
GNSS systems	standalone GPS, GLONASS, BeiDou and Galileo	

GPS Protocols	NMEA 0183 V3.0	
Acquisition sensitivity (dBm) - Cold-start	-145	• Qualcomm GPS RF conducted sensitivity is defined at the measurement level: the lowest GPS signal level (S, in dBm) at the antenna port for which the device can still detect an in-view satellite 50% of the time. • Acquisition/tracking sensitivity performance figures assume an open sky with an active-patch GPS antenna and a 2.5 dB noise figure.
Tracking sensitivity (dBm)	-160	
Accuracy in open sky	< 2m CEP-50	Open sky, 1Hz tracking
Standalone time to first fix (TTFF) (hot/warm/cold)	1s/29s/32s	
Total number of SVs available	~ 55 SVs	

2.9. Mechanical Specifications

2.9.1. Dimensions

The LM940 module's overall dimensions are:

- Length: 50.95 mm, +/- 0.15 mm tolerance
- Width: 30.00 mm, +/- 0.15 mm tolerance
- Thickness: 2.70 mm, +/- 0.15 mm tolerance

2.9.2. Weight

The nominal weight of the LM940 module is 9.6 gram.

2.10. Environmental Requirements

2.10.1. Temperature Range

		Note
Operating Temperature Range	–20°C ~ +55°C	This range is defined by 3GPP (the global standard for wireless mobile communication). Telit guarantees its modules to comply with all

		Note
		the 3GPP requirements and to have full functionality of the module with in this range.
	–40°C ~ +85°C	Telit guarantees full functionality within this range as well. However, there may possibly be some performance deviations in this extended range relative to 3GPP requirements, which means that some RF parameters may deviate from the 3GPP specification in the order of a few dB. For example: receiver sensitivity or maximum output power may be slightly degraded. Even so, all the functionalities, such as call connection, SMS, USB communication, UART activation etc., will be maintained, and the effect of such degradations will not lead to malfunction.
Storage and non-operating Temperature Range	–40°C ~ +85°C	

2.10.2. RoHS Compliance

As a part of the Telit corporate policy of environmental protection, the LM940 complies with the RoHS (Restriction of Hazardous Substances) directive of the European Union (EU directive 2011/65/EU).

3. PINS ALLOCATION

3.1. Pin-out

Information – The only difference between LM940 1.0 and LM940 2.0 is the pin-out.

Pins highlighted in Blue show that these pins are assigned differently to LM940 1.0 and LM940 2.0.

Otherwise they support same features and functions.

LM940 1.0 Pin-out

Pin	Signal	I/O	Function	Type	Comment
USB HS 2.0 Communication Port					
38	USB_D+	I/O	USB 2.0 Data Plus	Analog	
36	USB_D-	I/O	USB 2.0 Data Minus	Analog	
USB SS 3.0 Communication Port					
25	USB_SS_TX_P	O	USB 3.0 super-speed transmit – plus	Analog	
23	USB_SS_TX_M	O	USB 3.0 super-speed transmit – minus	Analog	
33	USB_SS_RX_P	I	USB 3.0 super-speed receive – plus	Analog	
31	USB_SS_RX_M	I	USB 3.0 super-speed receive – minus	Analog	
SIM Card Interface 1					

8	SIMVCC1	O	Supply output for an external UIM1 card	1.8V / 2.85V	Power
10	SIMIO1	I/O	Data connection with an external UIM1 card	1.8V / 2.85V	
12	SIMCLK1	O	Clock output to an external UIM1 card	1.8V / 2.85V	
14	SIMRST1	O	Reset output to an external UIM1 card	1.8V / 2.85V	
SIM Card Interface 2					
13	SIMVCC2	O	Supply output for an external UIM2 card	1.8 / 2.85V	Power
19	SIMIO2	I/O	Data connection with an external UIM2 card	1.8 / 2.85V	
17	SIMCLK2	O	Clock output to an external UIM2 card	1.8 / 2.85V	
7	SIMRST2	O	Reset output to an external UIM2 card	1.8 / 2.85V	
Digital I/O (GPIOs)					
3	GPIO_01	I/O	General purpose I/O Can be used as SIMIN1	1.8V	
5	GPIO_02	I/O	General purpose I/O Can be used as SIMIN2	1.8V	
44	GPIO_03	I/O	General purpose I/O	1.8V	
46	GPIO_04	I/O	General purpose I/O	1.8V	Internal 1.8V Pull-up

45	GPIO_05	I/O	General purpose I/O	1.8V	
47	GPIO_06	I/O	General purpose I/O	1.8V	
49	GPIO_07	I/O	General purpose I/O	1.8V	
51	GPIO_08	I/O	General purpose I/O	1.8V	
Control Signal					
1	PCIE_WAKE_N	O	PCIe wake-up	1.8V	
20	W_DISABLE_N	I	RF disable	Open-drain	Internal VBATT Pull-up
42	WAN_LED_N	O	LED control	Open-drain	
Miscellaneous Functions					
11	VREG_L6_1P8	O	Reference Voltage	1.8V	Power
22	SYSTEM_RESET_N	I	Reset Input	1.8V	
I2C Interface					
30	I2C_SCL	O	I2C Clock	1.8V	
32	I2C_SDA	I/O	I2C Data	1.8V	
Power Supply					
2	VBATT	I	Power supply	Power	
24	VBATT	I	Power supply	Power	
39	VBATT	I	Power supply	Power	

41	VBATT	I	Power supply	Power
52	VBATT	I	Power supply	Power
GROUND				
4	GND	-	Ground	Ground
9	GND	-	Ground	Ground
15	GND	-	Ground	Ground
18	GND	-	Ground	Ground
21	GND	-	Ground	Ground
26	GND	-	Ground	Ground
27	GND	-	Ground	Ground
29	GND	-	Ground	Ground
34	GND	-	Ground	Ground
35	GND	-	Ground	Ground
37	GND	-	Ground	Ground
40	GND	-	Ground	Ground
43	GND	-	Ground	Ground
50	GND	-	Ground	Ground
Reserved				
6	Reserved	-	Reserved (NC)	
16	Reserved	-	Reserved (NC)	

28	Reserved	-	Reserved (NC)
48	Reserved	-	Reserved (NC)

LM940 2.0 Pin-out

Pin	Signal	I/O	Function	Type	Comment
USB HS 2.0 Communication Port					
38	USB_D+	I/O	USB 2.0 Data Plus	Analog	
36	USB_D-	I/O	USB 2.0 Data Minus	Analog	
USB SS 3.0 Communication Port					
25	USB_SS_TX_P	O	USB 3.0 super-speed transmit – plus	Analog	
23	USB_SS_TX_M	O	USB 3.0 super-speed transmit – minus	Analog	
33	USB_SS_RX_P	I	USB 3.0 super-speed receive – plus	Analog	
31	USB_SS_RX_M	I	USB 3.0 super-speed receive – minus	Analog	
SIM Card Interface 1					
8	SIMVCC1	O	Supply output for an external UIM1 card	1.8V / 2.85V	Power
10	SIMIO1	I/O	Data connection with an external UIM1 card	1.8V / 2.85V	
12	SIMCLK1	O	Clock output to an external UIM1 card	1.8V / 2.85V	

14	SIMRST1	O	Reset output to an external UIM1 card	1.8V / 2.85V	
SIM Card Interface 2					
16	SIMVCC2	O	Supply output for an external UIM2 card	1.8 / 2.85V	Power
19	SIMIO2	I/O	Data connection with an external UIM2 card	1.8 / 2.85V	
17	SIMCLK2	O	Clock output to an external UIM2 card	1.8 / 2.85V	
6	SIMRST2	O	Reset output to an external UIM2 card	1.8 / 2.85V	
Digital I/O (GPIOs)					
3	GPIO_01	I/O	General purpose I/O Can be used as SIMIN1	1.8V	
5	GPIO_02	I/O	General purpose I/O Can be used as SIMIN2	1.8V	
44	GPIO_03	I/O	General purpose I/O	1.8V	
46	GPIO_04	I/O	General purpose I/O	1.8V	Internal 1.8V Pull-up
45	GPIO_05	I/O	General purpose I/O	1.8V	
47	GPIO_06	I/O	General purpose I/O	1.8V	
49	GPIO_07	I/O	General purpose I/O	1.8V	

51	GPIO_08	I/O	General purpose I/O	1.8V	
Control Signal					
1	PCIE_WAKE_N	O	PCIe wake-up	1.8V	
20	W_DISABLE_N	I	RF disable	Open-drain	Internal VBATT Pull-up
42	WAN_LED_N	O	LED control	Open-drain	
Miscellaneous Functions					
28	VREG_L6_1P8	O	Reference Voltage	1.8V	Power
48	SYSTEM_RESET_N	I	Reset Input	1.8V	
I2C Interface					
30	I2C_SCL	O	I2C Clock	1.8V	
32	I2C_SDA	I/O	I2C Data	1.8V	
Power Supply					
2	VBATT	I	Power supply	Power	
24	VBATT	I	Power supply	Power	
39	VBATT	I	Power supply	Power	
41	VBATT	I	Power supply	Power	
52	VBATT	I	Power supply	Power	
GROUND					
4	GND	-	Ground	Ground	
9	GND	-	Ground	Ground	

15	GND	-	Ground	Ground
18	GND	-	Ground	Ground
21	GND	-	Ground	Ground
26	GND	-	Ground	Ground
27	GND	-	Ground	Ground
29	GND	-	Ground	Ground
34	GND	-	Ground	Ground
35	GND	-	Ground	Ground
37	GND	-	Ground	Ground
40	GND	-	Ground	Ground
43	GND	-	Ground	Ground
50	GND	-	Ground	Ground
Reserved				
7	Reserved	-	Reserved (NC)	
11	Reserved	-	Reserved (NC)	
13	Reserved	-	Reserved (NC)	
22	Reserved	-	Reserved (NC)	

Information – If the I2C interface is not used, the signals can be left floating.

Information – Unless otherwise specified, RESERVED pins must be left unconnected (Floating).

3.2. LM940 Signals That Must Be Connected

Below table specifies the LM940 signals that must be connected for debugging purposes even if not used by the end application:

Mandatory Signals

Pin	Signal	Notes
2, 24, 39, 41, 52	VBATT	
4, 9, 15, 18, 21, 26, 27, 29, 34, 35, 37, 40, 43, 50	GND	
38	USB_D+	If not used, connect to a test point or an USB connector
36	USB_D-	If not used, connect to a test point or an USB connector

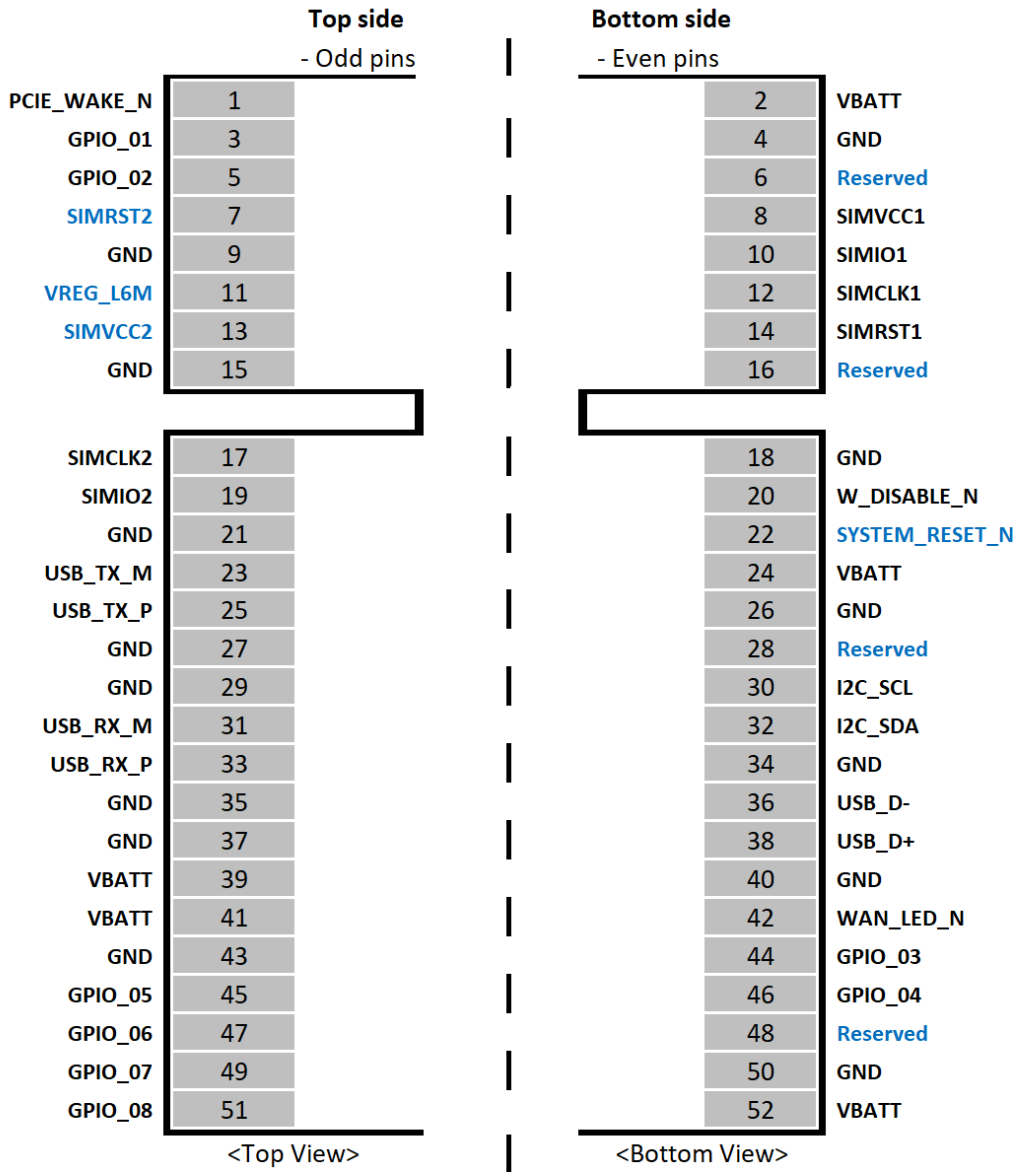
3.3. Pin Layout

Information – The only difference between LM940 1.0 and LM940 2.0 is the pin-out.

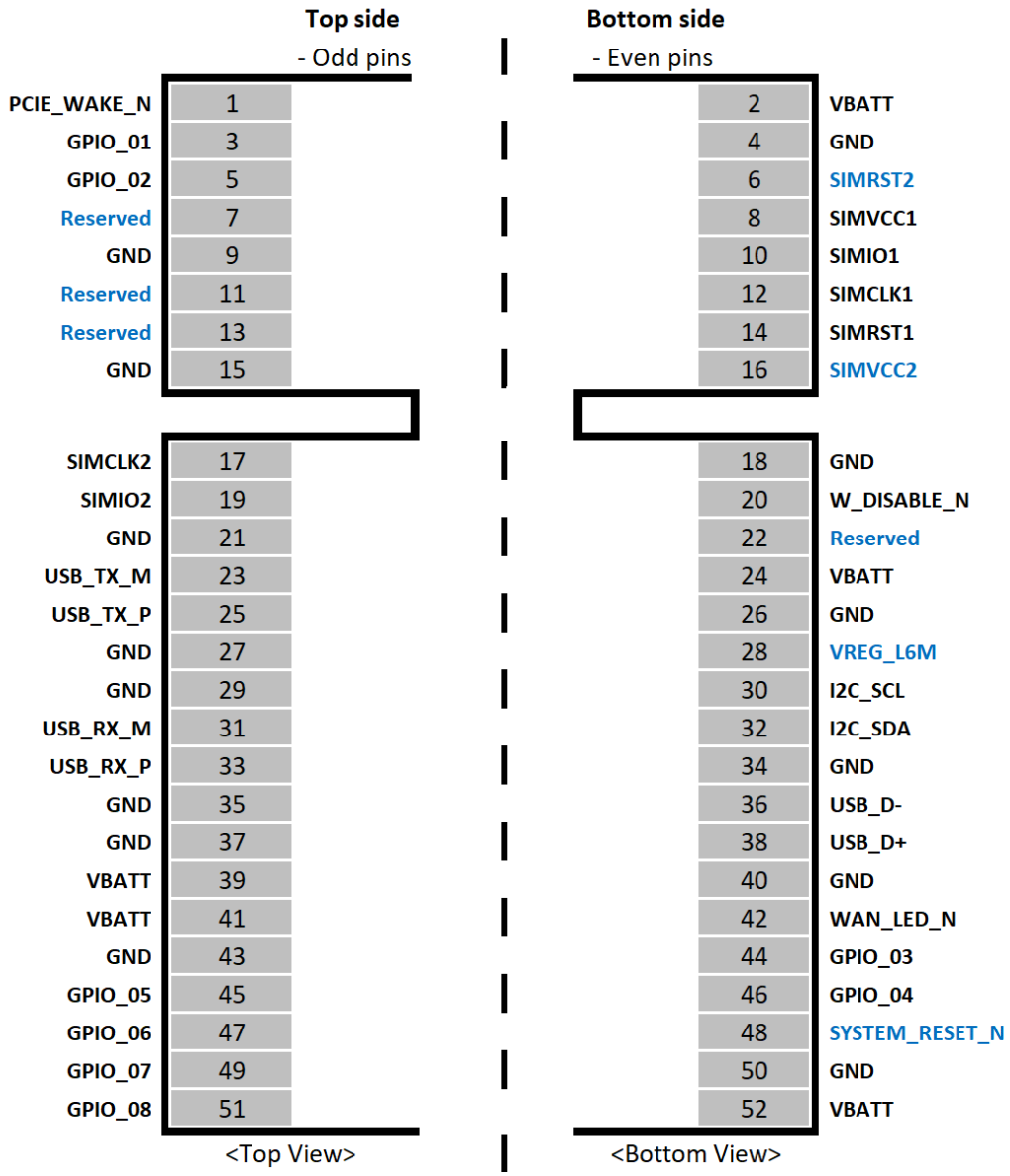
Pins highlighted in Blue show that these pins are assigned differently to LM940 1.0 and LM940 2.0.

Otherwise they support same features and functions.

LM940 1.0 Pin Layout



LM940 2.0 Pin Layout



4. POWER SUPPLY

The power supply circuitry and board layout are very important parts of the full product design, with critical impact on the overall product performance. Read the following requirements and guidelines carefully to ensure a good and proper design.

4.1. Power Supply Requirements

The LM940 power requirements are as follows:

Power Supply Requirements

Nominal supply voltage	3.3V
Supply voltage range	3.10V – 3.60V
Maximum ripple on module input supply	30 mV

4.2. Power Consumption

Below table provides typical current consumption values of LM940 for various operation modes.

LM940 Current Consumption

Mode	Average [Typ.]	Mode Description
IDLE Mode		
IDLE Mode	60.0 mA	No call connection USB3.0 is connected to a host
Operative Mode (LTE)		
LTE (22 dBm)	750 mA	LTE data call (Non-CA BW 5MHz, RB=1)
	1250 mA	LTE data call (CA_3A+7A+20A, 20MHz+20MHz+20MHz, Full RB, 256QAM DL / 64QAM UL, FDD 600Mbps DL / 75Mbps UL)
Operative Mode (WCDMA)		
WCDMA Voice	650 mA	WCDMA voice call (Tx = 23 dBm)
WCDMA HSPA (22 dBm)	650 mA	WCDMA data call (DC-HSDPA up to 42 Mbps, Max Throughput)

* Worst/best case current values depend on network configuration - not under module control.

** Applied MPR –2dB 16-QAM full RB

*** 3.3 voltage / room temperature

Information – The electrical design for the power supply must ensure a peak current output of at least 2A.

I

4.3. General Design Rules

The principal guidelines for the Power Supply Design embrace three different design steps:

- Electrical design
- Thermal design
- PCB layout

4.3.1. Electrical Design Guidelines

The electrical design of the power supply depends strongly on the power source where this power is drained.

4.3.1.1. + 5V Input Source Power Supply – Design Guidelines

- The desired output for the power supply is 3.3V. So, being the difference between the input and desired output voltage not large, a linear regulator can be used. A switching power supply is preferred to reduce power consumption.
- When using a linear regulator, a proper heat sink must be provided to dissipate the heat generated.
- A bypass low ESR capacitor of adequate capacity must be provided to cut the current absorption peaks close to the LM940 module. A 100 µF tantalum capacitor is usually suitable on VBATT.
- Verify the low ESR capacitor on the power supply output (usually a tantalium one) is rated at least 10V.
- A protection diode must be inserted close to the power input to protect the LM940 module from power polarity inversion.

4.3.2. Thermal Design Guidelines

The thermal design for the power supply heat sink must be done with the following specifications:

- Average current consumption during RF transmission @PWR level max in LM940 as shown in Section 4.2, Power Consumption table.

Information – The average consumption during transmission depends on the power level at which the device is requested to transmit via the network.

Therefore, the average current consumption can vary significantly.

Information – The thermal design for the power supply must be made keeping an average consumption at the maximum transmitting level during LTE/HSPA data transfer sessions.

Considering the very low current in Idle mode, especially if the Power Saving function is enabled, it can be assumed that - from the thermal point of view - the device absorbs significant current only during Data sessions.

In LTE/WCDMA/HSPA mode, the LM940 emits RF signals continuously during transmission. Therefore, special attention must be paid to dissipate the generated heat.

While designing the application board, the designer must make sure that the LM940 module is located on a large ground area of the application board for effective heat dissipation.

Information – The LM940 must be connected to the ground and metal chassis of the host board for best RF performance and thermal dispersion as well as to have module fixed.

- The two holes at the top of the module and the main ground of the host board must be fastened together.
- The shield cover of the module and the main board of the host board or the metal chassis of the host device should be connected with conductive materials.

4.3.3. Power Supply PCB layout Guidelines

As seen in the electrical design guidelines, the power supply must have a low ESR capacitor connected to the output to snub current peaks and a protection diode on the input to protect the supply from spikes and polarity inversion. The placement of these components is crucial for correct circuitry operation. A misplaced component can be useless or can even decrease the power supply performances.

- The bypass low ESR capacitor must be placed close to the LM940 power input pins, or if the power supply is of a switching type, it can be placed close to the inductor to cut the ripple, as long as the PCB trace from the capacitor to LM940 is wide enough to ensure a low voltage drop connection even during the 2A current peaks.
- The protection diode must be placed close to the input connector where the power source is drained.
- The PCB traces from the input connector to the power regulator IC must be wide enough to ensure that no significant voltage drops occur during the 2A current peaks.

- The PCB traces to LM940 and the bypass capacitor must be wide enough to ensure that no significant voltage drops occur when the 2A current peaks are absorbed. This is needed for the same above-mentioned reasons. Try to keep these traces as short as possible.
- The PCB traces connecting the switching output to the inductor and the switching diode must be kept as short as possible by placing the inductor and the diode very close to the power switching IC (only for the switching power supply). This is done to reduce the radiated field (noise) at the switching frequency (usually 100-500 kHz).
- Use a good common ground plane.
- Place the power supply on the board in a way to guarantee that the high current return paths in the ground plane do not overlap any noise sensitive circuitry, such as the microphone amplifier/buffer or earphone amplifier.
- The power supply input cables must be kept separate from noise sensitive lines, such as microphone/earphone cables.

4.4. RTC

The RTC within the LM940 module does not have a dedicated RTC supply pin. The RTC block is supplied by the VBATT supply.

If VBATT power is removed, RTC is not maintained so if maintaining an internal RTC is needed, VBATT must be supplied continuously.

4.5. Reference Voltage

1.8V regulated power supply output is provided as the reference voltage to a host board. This output is active when the module is ON and goes OFF when the module is shut down.

This table lists the VREG_L6_IP8 signal of LM940.

LM940 Reference Voltage

PIN	Signal	I/O	Function	Type	Comment
11	VREG_L6_1P8	O	Reference Voltage	power	1.8V

4.6. Internal LDO for GNSS bias

The LDO for GNSS bias is applied inside the LM940 model.

The voltage supply come from LM940's LDO to GNSS active antenna.

This table lists the LDO for GNSS bias of LM940.

LM940 Reference Voltage

Symbol	Parameter	Min	Typ	Max	Unit
$V_{GNSS\ DC\ bias}$	Voltage of Internal LDO for GNSS bias	2.9	3.1	3.3	[V]
$I_{GNSS\ DC\ bias}$	Current of Internal LDO for GNSS bias	-	-	50	[mA]

5. ELECTRICAL SPECIFICATIONS

5.1. Absolute Maximum Ratings – Not Operational

Caution – A deviation from the value ranges listed below may harm the LM940 module.

Absolute Maximum Ratings – Not Operational

Symbol	Parameter	Min	Max	Unit
VBATT	Battery supply voltage on pin VBATT	-0.5	+4.0	[V]

5.2. Recommended Operating Conditions

Recommended Operating Conditions

Symbol	Parameter	Min	Typ	Max	Unit
T_{amb}	Ambient temperature	-40	+25	+85	[°C]
VBATT	Battery supply voltage on pin VBATT	3.1	3.3	3.6	[V]
I_{VBATT+} I_{VBATT_PA}	Peak current to be used to dimension decoupling capacitors on pin VBATT	-	80	2500	[mA]

6. DIGITAL SECTION

6.1. Logic Levels

Unless otherwise specified, all the interface circuits of the LM940 are 1.8V CMOS logic.

Only USIM interfaces are capable of dual voltage I/O.

The following tables show the logic level specifications used in the LM940 interface circuits. The data specified in the tables below is valid throughout all drive strengths and the entire temperature ranges.

Caution – Do not connect LM940's digital logic signal directly to OEM's digital logic signal with a level higher than 2.3V for 1.8V CMOS signals.

6.1.1. 1.8V Pins – Absolute Maximum Ratings

Absolute Maximum Ratings – Not Functional

Parameter	Min	Max
Input level on any digital pin when on	--	+2.16V
Input voltage on analog pins when on	--	+2.16 V

6.1.2. 1.8V Standard GPIOs

Operating Range – Interface Levels (1.8V CMOS)

Parameter		Min	Max	Unit	Comment
VIH	Input high level	1.17V	2.1V	[V]	
VIL	Input low level	-0.3V	0.63V	[V]	
VOH	Output high level	1.35V	1.8V	[V]	
VOL	Output low level	0V	0.45V	[V]	
IIL	Low-level input leakage current	-1	--	[uA]	No pull-up
IIH	High-level input leakage current	--	1	[uA]	No pull-down
IILPU	Low-level input leakage current	-97.5	-27.5	[uA]	With pull-up

Parameter		Min	Max	Unit	Comment
IIHPD	High-level input leakage current	27.5	97.5	[uA]	With pull-down
CI/o	I/O capacitance	--	5	[pF]	

6.1.3. 1.8V SIM Card Pins

Operating Range – SIM Pins Working at 1.8V

Parameter		Min	Max	Unit	Comment
VIH	Input high level	1.26V	2.1V	[V]	
VIL	Input low level	-0.3V	0.36V	[V]	
VOH	Output high level	1.44V	1.8V	[V]	
VOL	Output low level	0V	0.4V	[V]	
IIL	Low-level input leakage current	--	1000	[uA]	No pull-up
IIH	High-level input leakage current	-20	20	[uA]	No pull-down

6.1.4. 2.85V Pins – Absolute Maximum Ratings

Absolute Maximum Ratings – Not Functional

Parameter	Min	Max
Input level on any digital pin when on	--	+3.42V
Input voltage on analog pins when on	--	+3.42 V

6.1.5. SIM Card Pins @2.85V

Operating Range – For SIM Pins Operating at 2.85V

Parameter		Min	Max	Unit	Comment
VIH	Input high level	1.995V	3.15V	[V]	
VIL	Input low level	-0.3V	0.57V	[V]	
VOH	Output high level	2.28V	2.85V	[V]	
VOL	Output low level	0V	0.4V	[V]	

Parameter		Min	Max	Unit	Comment
IIL	Low-level input leakage current	--	1000	[uA]	No pull-up
IIH	High-level input leakage current	-20	20	[uA]	No pull-down

6.2. Power On

The LM940 is automatically turning on when the VBATT is supplied.

Information – To turn on the LM940 module, the SYSTEM_RESET_N pin must not be asserted low.

6.2.1. Initialization and Activation State

After turning on the LM940 module, the LM940 is not instantly activated because the SW initialization process takes some time to complete.

For this reason, it is recommended not to communicate with the LM940 during the Initialization phase.

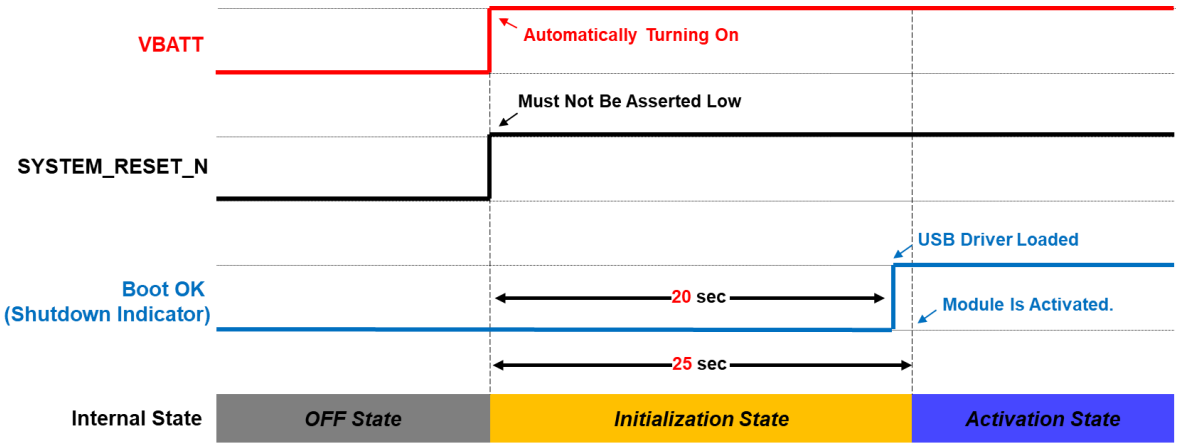
Boot OK(Shutdown Indicator) goes high at the time of AT command is available via USB. But this does not mean that it works fully.

As soon as the AT command interface is accessible via USB port, Boot OK line transitions to high but this does not imply that the device is fully operational yet.

One of GPIO pins can be configured as Shutdown indicator by means of AT#SHDNIND command: in that case, that GPIO will also work as Boot OK line when the module is booting.
Please refer to AT Commands Reference Guide for additional details.

In general, as shown in below figure, the LM940 becomes fully operational (in the Activation state) at least 35 seconds after the VBATT is supplied.

LM940 Initialization and Activation



Information – To verify if the LM940 has powered up properly, please check through one of two conditions below:

(1) LM940 and the host should be connected via USB. When USB driver is completely loaded, the module has powered on without problems and is ready to accept AT commands.
(2) Monitoring Boot OK (Shutdown Indicator). To use Boot OK (Shutdown Indicator), Boot OK(Shutdown Indicator) function must be enabled through AT#SHDNIND. (Refer to the AT User Guide document)

Information – Active low signals are labeled with a name that ends with "_N"

Information – To avoid a back-powering effect, it is recommended to avoid having any HIGH logic level signal applied to the digital pins of the module when it is powered OFF or during an ON/OFF transition.

6.3. Power Off

Power off the device can be done in three different ways:

- Graceful Shutdown by USB AT command AT#SHDN
- Fast Shutdown by GPIO triggered or USB AT command AT#FASTSHDN
- Unconditional Shutdown using the SYSTEM_RESET_N

6.3.1. Graceful Shutdown

To shutdown the LM940 module more safely, host can use the graceful shutdown function.

The graceful shutdown can be triggered by:

- AT command via USB

6.3.1.1. Graceful Shutdown by AT command

To gracefully shutdown the LM940 module,

First, shutdown AT command must be sent via a USB communication.

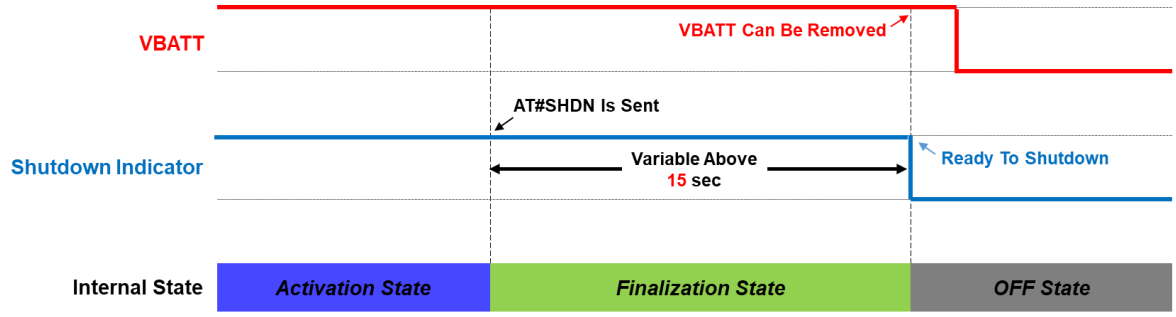
Once the shutdown command is sent, the LM940 module enters finalization state, terminates active processes and prepares to turn off safely.

As shown in below figure, when the module is ready to be turned off, it will be indicated via Shutdown Indicator.

As shown in the diagram below, Shutdown indicator will indicate when the module is ready to be turned off.

Please refer to the AT User Guide for more detail about AT#SHDN and AT#SHDNIND.

Graceful Shutdown by AT Command



The DTE should monitor the status of Shutdown Indicator to proceed graceful power-off.

Information – VBATT must not be removed before Shutdown Indicator goes LOW.

Warning – Not following the recommended shut-down procedures might damage the device and consequently void the warranty.

6.3.2. Fast Shutdown

For a quicker shutdown of the LM940 module, the host can use the fast shutdown functionFast shutdown can be triggered by:

- AT command via USB
- GPIO

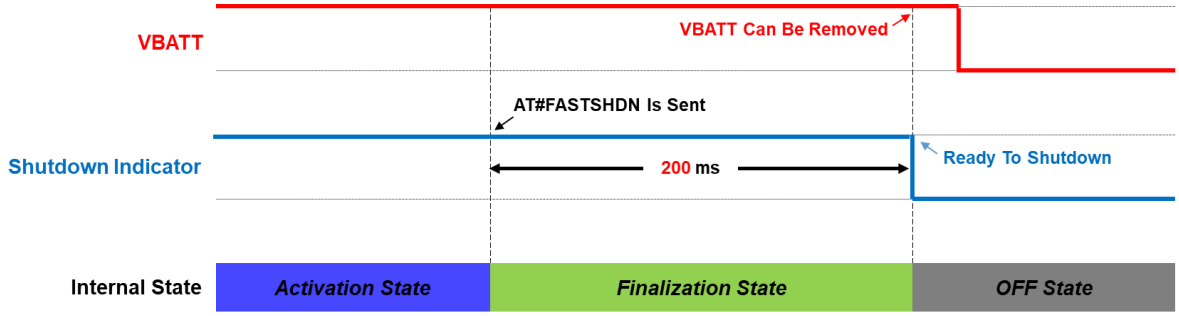
6.3.2.1. Fast Shutdown by AT command

Once AT#FASTSHDN command is sent through the USB port, the LM960 enters finalization state, terminates active processes and preparing to safely turn off.

As shown in the diagram below, when the module is ready to be turned off, it will be indicated via Shutdown Indicator.

One of GPIO lines can be configured as Shutdown Indicators function by means of AT commands: please refer to the AT User Guide for more details about AT#FASTSHDN and AT#SHDNIND.

Fast Shutdown by AT command



The DTE should monitor the status of Shutdown Indicator to proceed fast power-off.

Information – VBATT must not be removed before Shutdown Indicator goes LOW.

Warning – Not following the recommended shut-down procedures might damage the device and consequently void the warranty.

6.3.2.2. Fast Shutdown by GPIO

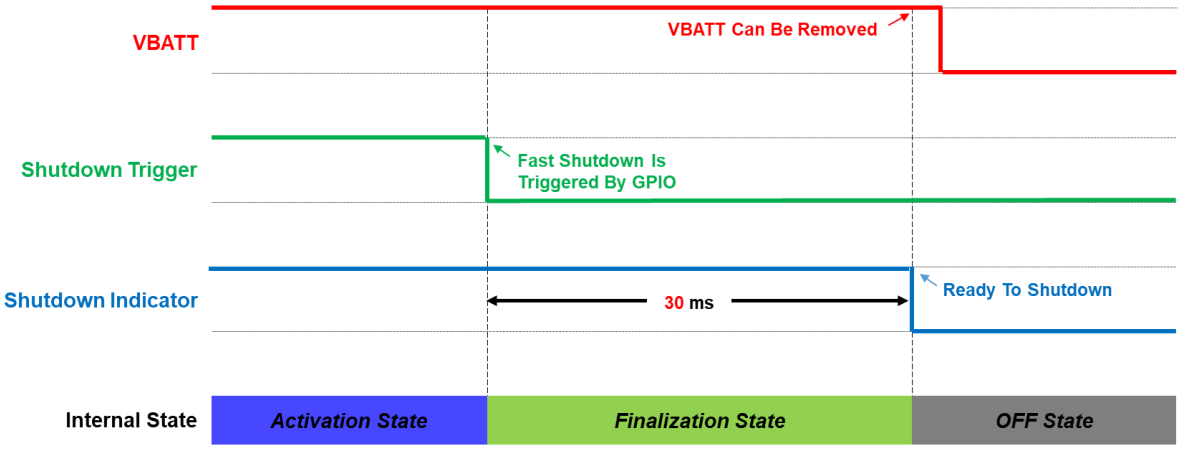
If properly configured, one of GPIO lines can be used as Fast Shutdown Trigger.

Once the Fast Shutdown Trigger senses a HIGH to LOW transition, fast shutdown is initiated.

Then the LM940 module enters finalization state, terminates active processes and prepares to turn off safely. As shown in below figure, when the module is ready to be turned off, it will be indicated via Shutdown Indicator.

Please refer to the AT User Guide for more detail about enable Shutdown Indicator and Fast Shutdown Trigger.

Fast Shutdown by GPIO



The DTE should monitor the status of Shutdown Indicator to proceed fast power-off.

Information – VBATT must not be removed before Shutdown Indicator goes LOW.

Warning – Not following the recommended shut-down procedures might damage the device and consequently void the warranty.

6.3.3. Unconditional Shutdown

To turn off the LM940, SYSTEM_RESET_N pad must be asserted low more than 1 seconds and then it should be kept low.

When the SYSTEM_RESET_N is asserted low more than 1 second, the LM940 enters finalization state and after the end of the shutdown process Shutdown Indicator will go to low.

Usually, it takes the LM940 less than 100 milliseconds from asserting SYSTEM_RESET_N until reaching a complete shutdown. The DTE should monitor the status of Shutdown Indicator to observe the actual power-off.

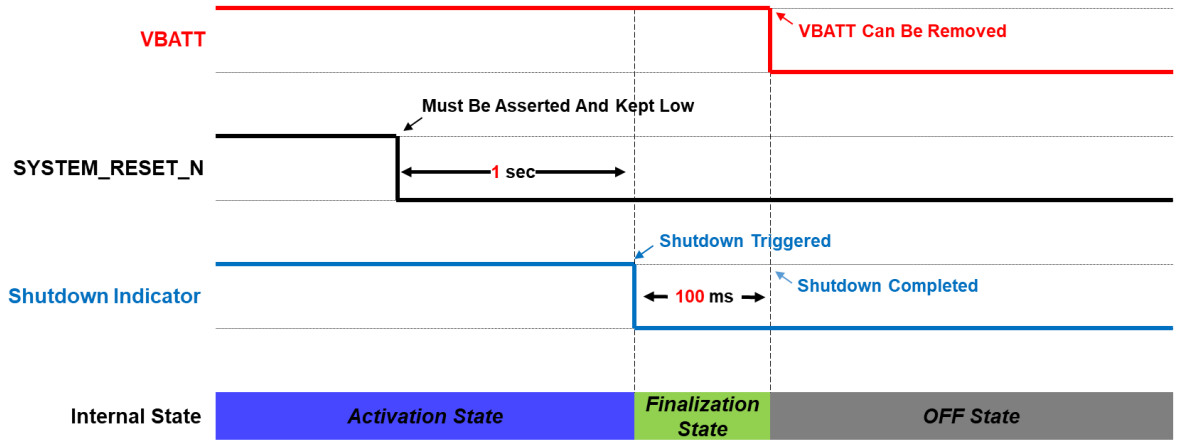
Information – To completely shut down the LM940 module, the SYSTEM_RESET_N pin must be asserted and kept low.

Otherwise, the LM940 will turn on again after shut down.

Information – To avoid a back-powering effect, it is recommended to avoid having any HIGH logic level signal applied to the digital pins of the module when it is powered OFF or during an ON/OFF transition.

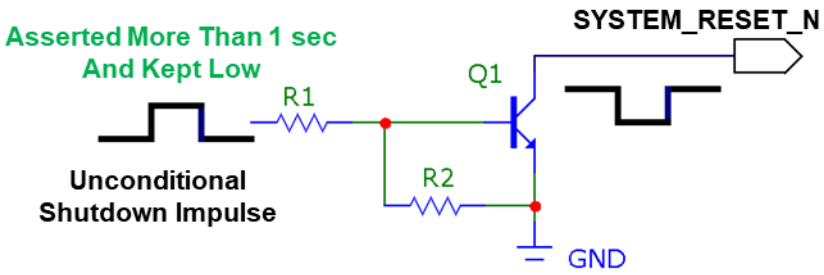
Warning – Not following the recommended shut-down procedures might damage the device and consequently void the warranty.

Shutdown by SYSTEM_RESET_N Pad



Below figure shows a simple circuit for this action.

Circuit for Shutdown by SYSTEM_RESET_N



6.4. Reset

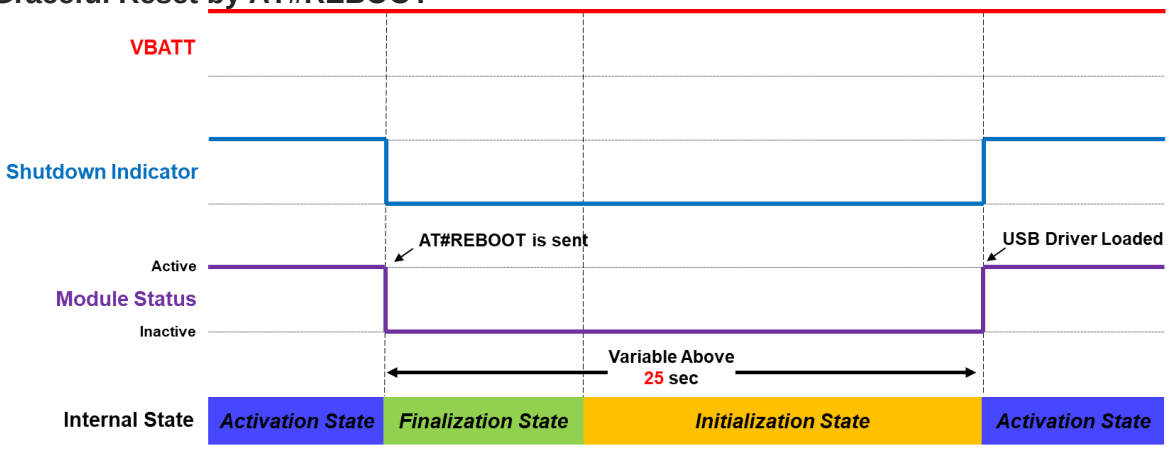
Reset the device can be done in two different ways:

- Graceful Reset by USB AT command AT#REBOOT
- Unconditional Reset using the SYSTEM_RESET_N

6.4.1. Graceful Reset

To gracefully restart the LM940 module, AT#REBOOT AT command must be sent via a USB communication.

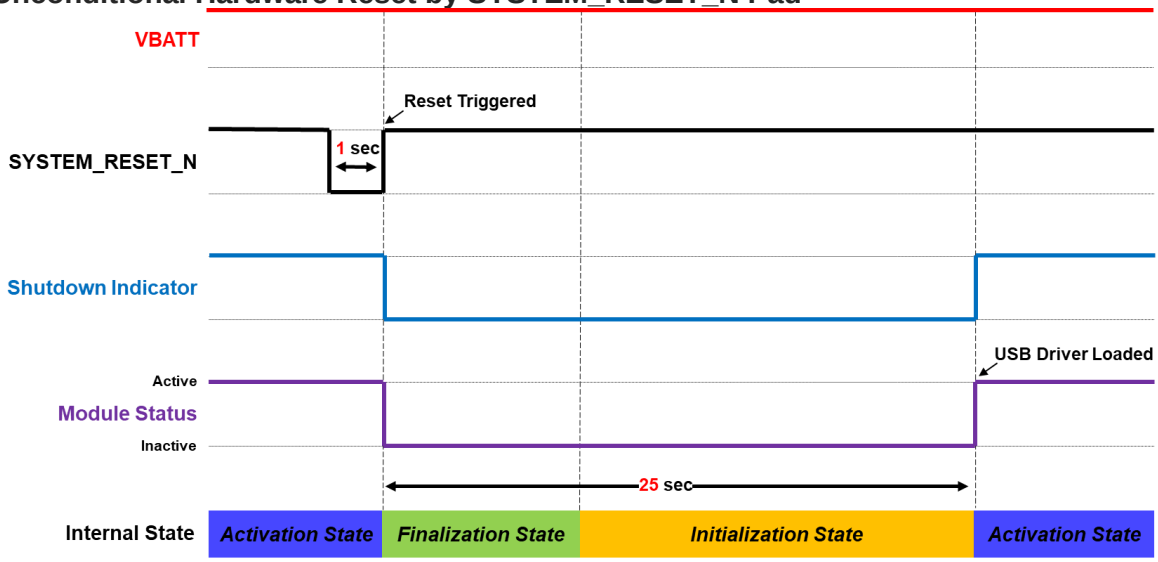
Graceful Reset by AT#REBOOT



6.4.2. Unconditional Hardware Reset

To unconditionally restart the LM940 module, the SYSTEM_RESET_N pin must be asserted low more than 1 seconds and then released.

Unconditional Hardware Reset by SYSTEM_RESET_N Pad



Information – The Unconditional Hardware Reset must be used only as an emergency exit procedure, and not as a normal power-off operation.

Information – Do not use any pull-up resistor on the RESET_N line or any totem pole digital output. Using a pull-up resistor may cause latch-up problems on the LM940 power regulator and improper functioning of the module. The RESET_N line must be connected only in an open-collector configuration.

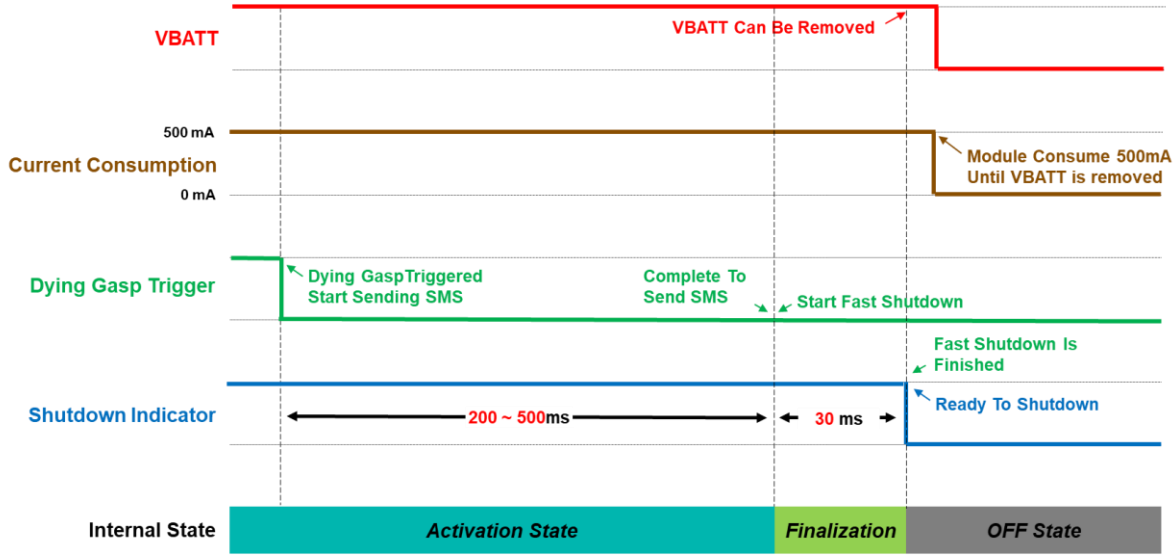
6.5. Dying Gasp

If any major issue occurs within the Host System, the host itself can use the dying gasp function by notifying the LM940 module.

One of GPIOs can be configured as Dying Gasp Trigger by means of AT commands.

Once the Dying Gasp Trigger receives a HIGH to LOW transition, the dying gasp procedure is triggered: the LM460 will send the specified SMS and then initiate fast shutdown.

Dying Gasp by GPIO, Max Power Non-CA , Current :500mA, 3.3V



Usually dying gasp feature is completed less than 1 second after triggered.

This may take longer depending on network conditions.

6.6. Communication ports

Below table summarizes all the hardware interfaces of the LM940 module.

LM940 Hardware Interfaces

Interface	LM940
USB	Super-speed USB3.0 with high-speed USB2.0
USIM	x2, dual voltage each (1.8V/2.85V)
Control Signals	W_DISABLE_N
GPIO	X8, GPIO
I2C	I2C (optional)
Antenna ports	2 for Cellular, 1 for GNSS

6.6.1. USB Interface

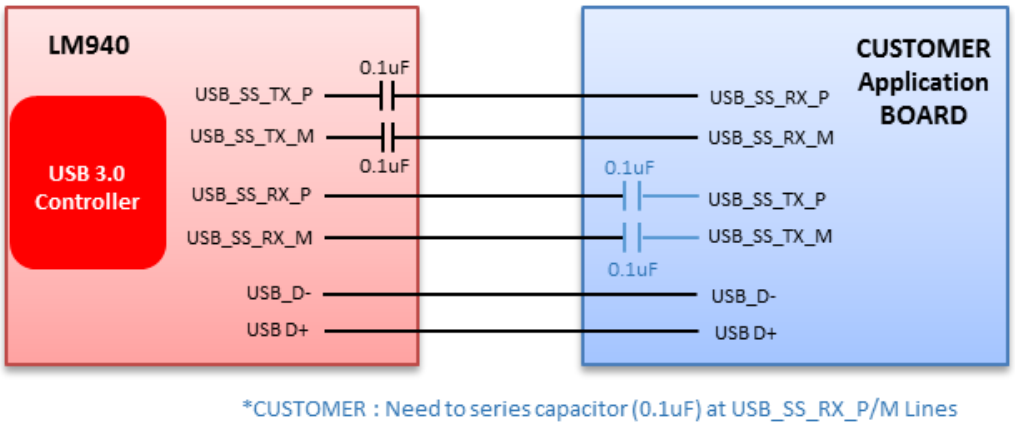
The LM940 module includes super-speed USB3.0 with high-speed USB2.0 backward compatibility. It is compliant with Universal Serial Bus Specification, Revision 3.0 and can be used for control and data transfers as well as for diagnostic monitoring and firmware update.

The USB port is typically the main interface between the LM940 module and OEM hardware.

USB 3.0 needs capacitors on the TX lines in both directions for AC coupling. In order to interface USB3.0 with an application board of customer, 0.1uF capacitors should be installed on USB_SS_RX_P/M lines of the LM940. There are already capacitors on USB_SS_TX_P/M lines inside LM940 module.

The suggested USB interface connection is the following:

Connection for USB Interface



*CUSTOMER : Need to series capacitor (0.1uF) at USB_SS_RX_P/M Lines

Information – The USB signal traces must be routed carefully. Minimize trace lengths, number of vias, and capacitive loading. The impedance value should be as close as possible to 90 Ohms differential.

Warning – At power-up, LM940 success to enumerate SS_USB interface. But if a hot-plug is attempted in case of SS_USB, then LM940 may fail to enumerate SS_USB.

Below table lists the USB interface signals.

USB Interface Signals

PIN	Signal	I/O	Function	Type	Comment
38	USB_D+	I/O	USB 2.0 Data Plus	Analog	
36	USB_D-	I/O	USB 2.0 Data Minus	Analog	
33	USB_SS_RX_P	I	USB 3.0 super-speed receive – plus	Analog	
31	USB_SS_RX_M	I	USB 3.0 super-speed receive – minus	Analog	
25	USB_SS_TX_P	O	USB 3.0 super-speed transmit – plus	Analog	
23	USB_SS_TX_M	O	USB 3.0 super-speed transmit – minus	Analog	

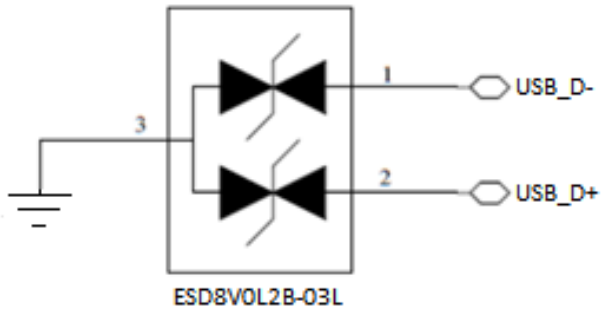
Information – Even if USB communication is not used, it is still highly recommended to place an optional USB connector on the application board.

At least test points of the USB signals are required since the USB physical communication is needed in the case of SW update.

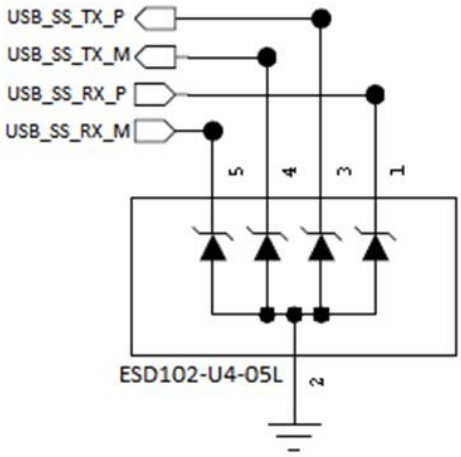
Information – Consider placing a low-capacitance ESD protection component to protect LM940 against ESD strikes

If an ESD protection should be added, it is suggested to connect it as follows:

ESD Protection for USB2.0



ESD Protection for USB3.0



6.6.2. SIM Interface

The LM940 supports two external SIM interfaces (1.8V or 2.85V).

Information – LM940 HW versions 1.0 and 2.0 have a different SIM2 pinout.

Below table lists the SIM interface signals.

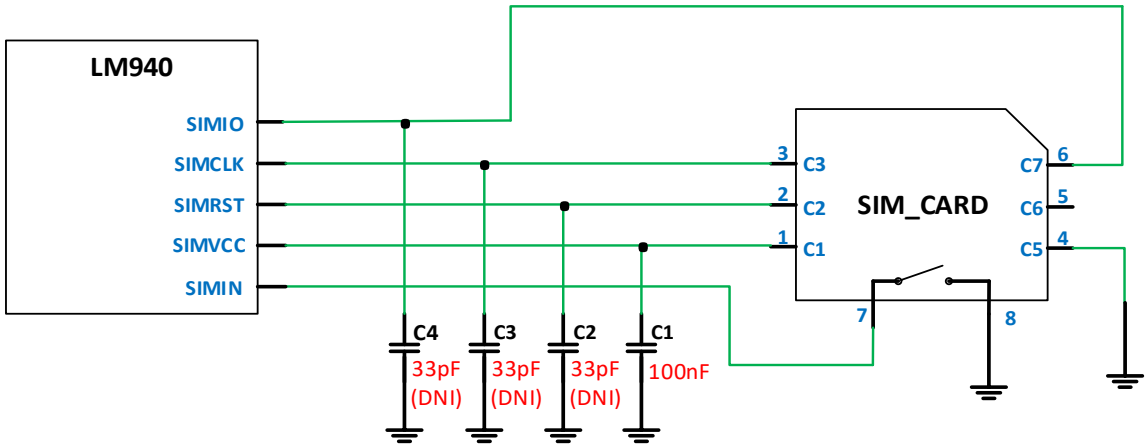
SIM Interface Signals

PIN	Signal	I/O	Function	Type	Comment
SIM Card Interface 1					
8	SIMVCC1	O	Supply output for an external UIM1 card	1.8V / 2.85V	Power
10	SIMIO1	I/O	Data connection with an external UIM1 card	1.8V / 2.85V	
12	SIMCLK1	O	Clock output to an external UIM1 card	1.8V / 2.85V	
14	SIMRST1	O	Reset output to an external UIM1 card	1.8V / 2.85V	
SIM Card Interface 2 – LM940 1.0					
13	SIMVCC2	O	Supply output for an external UIM2 card	1.8 / 2.85V	Power
19	SIMIO2	I/O	Data connection with an external UIM2 card	1.8 / 2.85V	
17	SIMCLK2	O	Clock output to an external UIM2 card	1.8 / 2.85V	
7	SIMRST2	O	Reset output to an external UIM2 card	1.8 / 2.85V	
SIM Card Interface 2 – LM940 2.0					
6	SIMVCC2	O	Supply output for an external UIM2 card	1.8 / 2.85V	Power
19	SIMIO2	I/O	Data connection with an external UIM2 card	1.8 / 2.85V	
17	SIMCLK2	O	Clock output to an external UIM2 card	1.8 / 2.85V	
16	SIMRST2	O	Reset output to an external UIM2 card	1.8 / 2.85V	
Digital I/O (GPIOs)					
3	GPIO_01	I	UIM1 Card Present Detect	1.8V	GPIO_01 can be used as SIMIN1
5	GPIO_02	I	UIM2 Card Present Detect	1.8V	GPIO_02 can be used as SIMIN2

6.6.2.1. SIM Schematic Example

The following Figures illustrate in particular how the application interface should be designed.

SIM Schematics



Information – LM940 contains an internal pull-up resistor on SIMIO. It is not necessary to install external pull – up resistor.

6.6.3. Control Signals

The LM940 supports the following control signals:

- W_DISABLE_N

Below table lists the control signals of LM940.

Module Control Signal

PIN	Signal	I/O	Function	Type	Comment
20	W_DISABLE_N	I	RF disable (airplane mode)	1.8V	

6.6.3.1. W_DISABLE_N

The W_DISABLE_N signal is provided to make the LM940 goes into the airplane mode:

- Enter into the airplane mode: Low
- Normal operating mode: High or Leave the W_DISABLE_N not connected

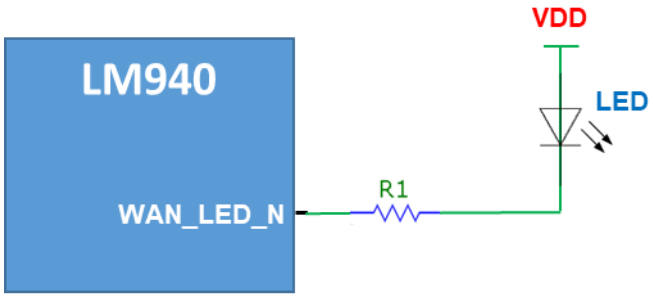
LM940 contains an internal VBATT(Nominal 3.3V) pull-up resistor on W_DISABLE_N.

6.6.3.2. WAN_LED_N

The WAN_LED_N signal drives the LED output.

The recommended WAN_LED_N connection is the following:

Recommended WAN_LED_N connection



R1 and VDD determine the brightness of LED and forward current.

When VDD is 3.3V and LED's forward voltage is 2.0V, it is recommended to use the value of R1 from 66 ohm to 250 ohm.

But please determine it in considering the specification of the LED to use.

Information – If enable the LED function and connect the LED to the WAN_LED_N pin, current consumption may be increased.

6.6.4. General Purpose I/O

The general-purpose I/O pins can be configured to act in three different ways:

- Input
- Output
- Dedicate Function (Customer Requirement)

Input pins can only be read and report digital values (high or low) present on the pin at the read time. Output pins can only be written or queried and set the value of the pin output.

The following GPIOs are always available as a primary function on the LM940.

Below table lists the GPIO signals of LM940.

GPIOs

Pin no.	Signal	I/O	Function	Type	Drive Strength
3	GPIO_01	I/O	Configurable GPIO	Pull-Down 1.8V	2-16 mA
5	GPIO_02	I/O	Configurable GPIO	Pull-Down 1.8V	2-16 mA
44	GPIO_03	I/O	Configurable GPIO	Pull-Down 1.8V	2-16 mA
46	GPIO_04	I/O	Configurable GPIO	Pull-Up 1.8V	2-16 mA

Pin no.	Signal	I/O	Function	Type	Drive Strength
45	GPIO_05	I/O	Configurable GPIO	Pull-Down 1.8V	2-16 mA
47	GPIO_06	I/O	Configurable GPIO	Pull-Down 1.8V	2-16 mA
49	GPIO_07	I/O	Configurable GPIO	Pull-Down 1.8V	2-16 mA
51	GPIO_08	I/O	Configurable GPIO	Pull-Down 1.8V	2-16 mA

6.6.4.1. Using a GPIO Pin as Input

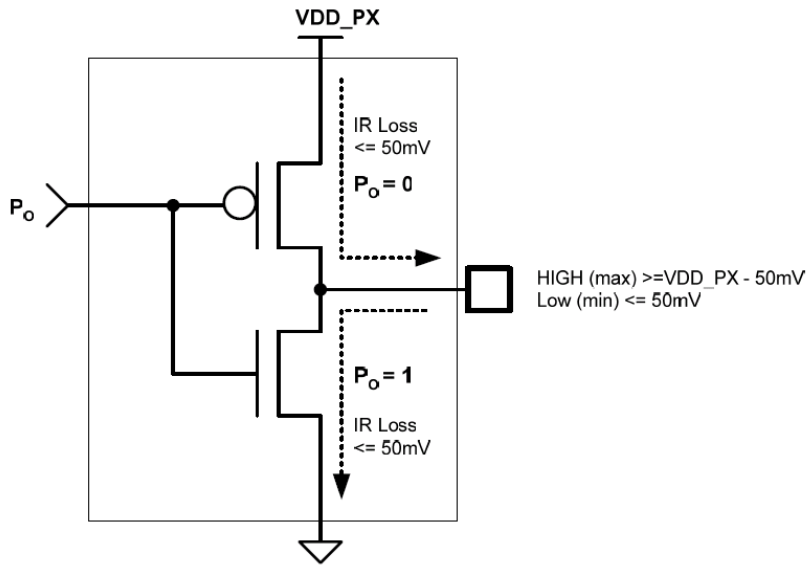
GPIO pins, when used as inputs, can be tied to a digital output of another device and report its status, provided the device interface levels are compatible with the GPIO 1.8V CMOS levels.

If a digital output of a device is tied to GPIO input, the pin has interface levels different than 1.8V CMOS. It can be buffered with an open collector transistor with a 47 kΩ pull-up resistor to 1.8V.

6.6.4.2. Using a GPIO Pin as Output

GPIO pins, when used as outputs, can drive 1.8V CMOS digital devices or compatible hardware. When set as outputs, the pins have a push-pull output, and therefore the pull-up resistor can be omitted.

GPIO Output Pin Equivalent Circuit



6.6.4.3. Dedicated I/O

In order to use SIMIN functions, host must use GPIO_01/GPIO_02.

Dedicated I/O

Pin no.	Signal	IO/Level	Dedicated Function
3	GPIO_01	Input/1.8V	Can be used as SIMIN1 function
5	GPIO_02	Input/1.8V	Can be used as SIMIN2 function

Below functions are not dedicated to specific GPIO.
Custormer use one of GPIOs (GPIO_03 to GPIO_08) as these functions by AT command.

- Boot OK
- Shutdown Indicator
- Shutdown Trigger
- Dying Gasp Trigger

Not Dedicated I/O

Pin no.	Signal	IO/Level	Dedicated Function
44	GPIO_03	I/O, 1.8V	Can be used as specific functions.
46	GPIO_04	I/O, 1.8V	Can be used as specific functions.
45	GPIO_05	I/O, 1.8V	Can be used as specific functions.
47	GPIO_06	I/O, 1.8V	Can be used as specific functions.
49	GPIO_07	I/O, 1.8V	Can be used as specific functions.
51	GPIO_08	I/O, 1.8V	Can be used as specific functions.

6.6.5. I2C – Inter-integrated circuit

The LM940 supports an I2C interface. The table below lists the LM940 I2C signals.

Module I2C Signal

PIN	Signal	I/O	Function	Type	Comment
30	I2C_SCL	O	I2C Clock	CMOS 1.8V	
32	I2C_SDA	I/O	I2C Data	CMOS 1.8V	

The I2C interface is used for controlling peripherals inside the module (such as codec, etc.).

Information – I2C is supported only on from Modem side as SW emulation of I2C on GPIO lines.

Please contact Telit Customer support if you use it.

Information – If the I2C interface is not used, the signals can be left floating.

6.7. Using the Temperature Monitor Function

The Temperature Monitor permits to monitor the module's internal temperature and, if properly set (see the #TEMPSENS command in LM940 AT Commands Reference Guide), raises a GPIO to High Logic level when the maximum temperature is reached.

7. RF SECTION

7.1. Antenna requirements

The antenna connection is one of the most important aspect in the full product design as it strongly affects the product overall performance. Hence please read carefully and follow the requirements and the guidelines for a proper design.

The LM940 is provided with three RF connectors.

The available connectors are:

- Main RF antenna: TX/RX path
- Auxiliary RF antenna: Combined Diversity and GNSS
- GNSS RF antenna: Dedicated GNSS

7.2. Main Antenna Requirements

The antenna for the LM940 device must meet the following requirements:

WCDMA / LTE Antenna Requirements

Frequency range	Depending on frequency band(s) supported by the network operator, the customer shall use the most suitable antenna for that/those band(s) The bands supported by the LM940 is provided in Section 2.2, Product Variants and Frequency Bands.
Impedance	50 Ohm
Input power	> 24 dBm average power in WCDMA & LTE
VSWR absolute max	<= 10:1
VSWR recommended	<= 2:1

7.3. Antenna Diversity Requirements

This product includes an input for a second Rx antenna to improve radio sensitivity. The function is called Antenna Diversity.

Antenna Diversity Requirements

Frequency range	Depending on frequency band(s) supported by the network operator, the customer shall use the most suitable antenna for that/those band(s) The bands supported by the LM940 is provided in Section 2.2, Product Variants and Frequency Bands.
Impedance	50Ω
VSWR recommended	≤ 2:1

The second Rx antenna should not be located in the close vicinity of main antenna. In order to improve Diversity Gain, Isolation and reduce mutual interaction, the two antennas should be located at the maximum reciprocal distance possible, taking into consideration the available space into the application. For the same reason, the Rx antenna should also be cross-polarized with respect to the main antenna.
Isolation between main antenna and Rx antenna must be at least 10 dB in all uplink frequency bands.

Envelope Correlation Coefficient (ECC) value should be as close as possible to zero, for best diversity performance. ECC values below 0.5 on all frequency bands are recommended.

7.4. GNSS Receiver

The LM940 integrates a GNSS receiver that could be used in Standalone mode and in A-GPS (assisted GPS), according to the different configurations.

LM940 supports an active antenna.

Frequency range	• Wide-band GNSS: 1560–1606 MHz recommended • Narrow-band GPS: 1575.42 MHz ± 2 MHz minimum • Narrow-band Galileo: 1575.42 MHz ± 2 MHz minimum • Narrow-band BeiDou: 1561.098 MHz ± 2 MHz minimum • Narrow-band GLONASS: 1601.72 MHz ± 4.2 MHz minimum.
Gain	1.5 dBi < Gain < 3 dBi
Impedance	50 Ohm
Amplification	18 dB < Gain < 21 dB
Supply Voltage	3.1 V
Current consumption	20 mA Typical

7.4.1. GNSS RF Front End Design

The LM940 contains an integrated LNA and pre-select SAW filter.
This allows the module to work well with a passive GNSS antenna. If the antenna cannot be located near the LM940, then an active antenna (that is, an antenna with a low noise amplifier built in) can be used with an external dedicated power supply circuit.

GNSS receive path uses either the dedicated GNSS connector or the shared AUX connector.

NOTE – Please refer to the LM940 AT Commands Reference Guide, 80545ST10791A for detailed information about GNSS operating modes and GNSS Antenna selection.

7.5. Antenna connection

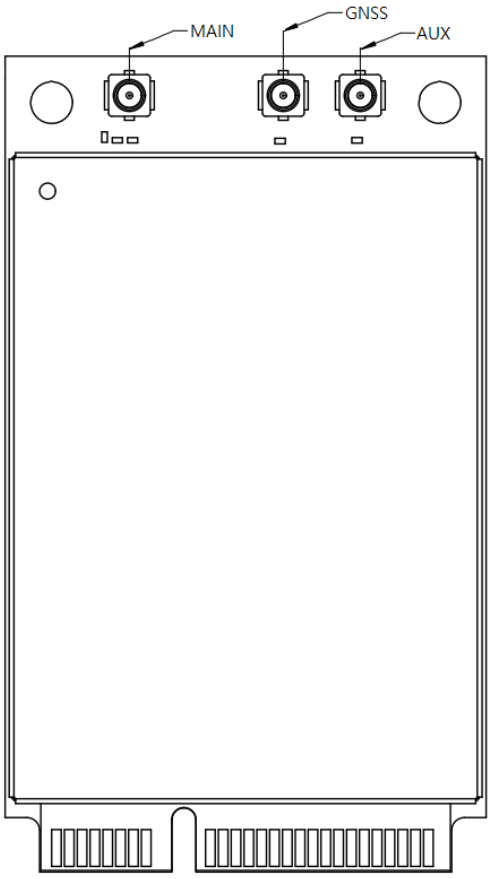
7.5.1. Antenna Connector

The LM940 is equipped with a set of 50 Ω RF U.FL. connectors from Hirose U.FL-R-SMT-1(10).

The available connectors are:

- Main RF antenna: TX/RX path
- Auxiliary RF antenna: Combined Diversity and GNSS
- GNSS RF antenna: Dedicated GNSS

See the picture on the below for their position on the interface.



For more information about mating connectors visit the website http://www.hirose-connectors.com/

7.5.2. Antenna Cable

Connecting cables between the module and the antenna must have 50 Ω impedance.
If the impedance of the module is mismatched, RF performance is reduced significantly.

If the host device is not designed to use the module's diversity or GNSS antenna, terminate the interface with a 50Ω load.

Minimize Antenna Cable Requirements

Impedance	50 Ohm
Max cable loss	0.5 dB
Avoid coupling with other signals.	

7.5.3. Antenna Installation Guidelines

- Install the antenna in a location with access to the network radio signal.
- The antenna must be installed such that it provides a separation distance of at least 20 cm from all persons and must not be co-located or operating in conjunction with any other antenna or transmitter.
- The antenna must not be installed inside metal cases.
- The antenna must be installed according to the antenna manufacturer's instructions.

Furthermore, if the device is developed for the US and/or Canada market, it must comply with the FCC and/or IC approval requirements.

Information

This device is to be used only for mobile and fixed application. The antenna(s) used for this transmitter must be installed to provide a separation distance of at least 20 cm from all persons and must not be co-located or operating in conjunction with any other antenna or transmitter. End-Users must be provided with transmitter operation conditions for satisfying RF exposure compliance. OEM integrators must ensure that the end user has no manual instructions to remove or install the LM940 module. Antennas used for this OEM module must not exceed gain of below table for mobile and fixed operating configurations.

In the event that these conditions cannot be met (for example certain laptop configurations or co-location with another transmitter), then the FCC/IC authorization is no longer considered valid and the FCC/IC ID cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC/IC authorization.

Manual Information to the End User

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module. The end user manual shall include all required regulatory information/warning as show in this manual.

8. MECHANICAL DESIGN

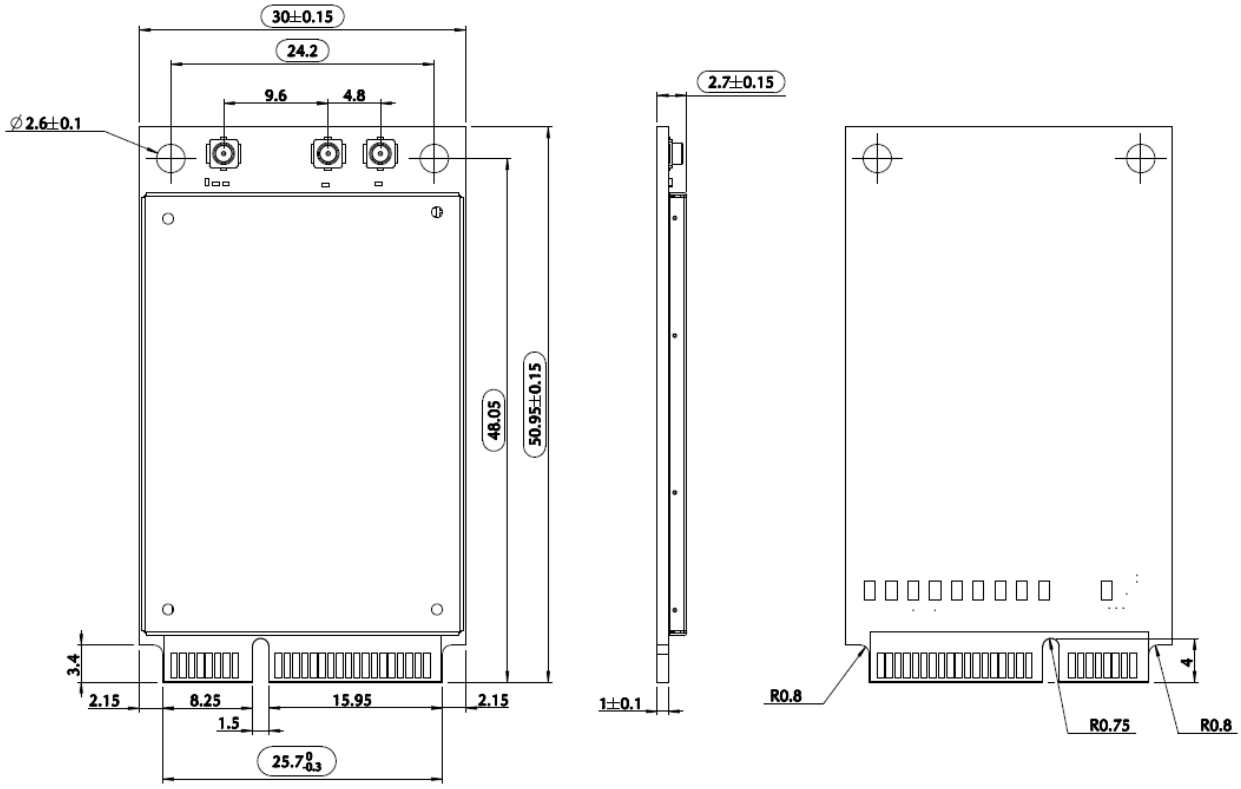
8.1. General

The LM940 module was designed to be compliant with a standard lead-free SMT process. Moreover, it is compatible with the Mini PCIe card 52-pin card edge-type connector.

8.2. Finishing & Dimensions

8.3. Drawing

This figure shows the mechanical dimensions of the LM940 module.



9. APPLICATION GUIDE

9.1. Debug of the LM940 Module in Production

To test and debug the mounting of the LM940 module, we strongly recommend to add several test points on the host PCB for the following purposes:

- Checking the connection between the LM940 itself and the application
- Testing the performance of the module by connecting it with an external computer

Depending on the customer application, these test pins include, but are not limited to the following signals:

- SYSTEM_RESET_N, W_DISABLE_N
- VBATT, GND
- VREG_L6_1P8
- USB_D-, USB_D+
- USB_SS_TX_M, USB_SS_TX_P, USB_SS_RX_M, USB_SS_RX_P

In addition, the following signals are also recommended (but not mandatory):

- GPIO_01, GPIO_02, GPIO_03, GPIO_04, GPIO_05, GPIO_06, GPIO_07, GPIO_08

9.2. Bypass Capacitor on Power Supplies

When a sudden voltage step is asserted to or a cut from the power supplies, the steep transition causes some reactions such as overshoot and undershoot. This abrupt voltage transition can affect the device causing it to not operate or to malfunction.

Bypass capacitors are needed to alleviate this behavior. The behavior can appear differently depending on the various applications. Customers must pay special attention to this issue when they design their application board.

The length and width of the power lines must be considered carefully, and the capacitance of the capacitors must be selected accordingly.

The capacitor will also prevent ripple of the power supplies and the switching noise caused in TDMA systems such as GSM.

Especially, a suitable bypass capacitor must be mounted on the following lines on the application board:

- VBATT

Recommended values are:

- 100uF for VBATT

Please note that capacitance mainly depends on the conditions of their application board.

Generally, additional capacitance is required when the power line is longer.
And if customers use the fast power down function, then more bypass capacitors should be mounted on the application board.

9.3. EMC Recommendations

EMC protection on the pins in the table below should be designed by application side according to the customer's requirement.

EMC Recommendations

Pin	Signal	I/O	Function	Type	Comment
USB HS 2.0 Communication Port					
38	USB_D+	I/O	USB 2.0 Data Plus	Analog	
36	USB_D-	I/O	USB 2.0 Data Minus	Analog	
USB SS 3.0 Communication Port					
33	USB_SS_RX_P	I	USB 3.0 super-speed receive – plus	Analog	
31	USB_SS_RX_M	I	USB 3.0 super-speed receive – minus	Analog	
25	USB_SS_TX_P	O	USB 3.0 super-speed transmit – plus	Analog	
23	USB_SS_TX_M	O	USB 3.0 super-speed transmit – minus	Analog	
SIM Card Interface 1					
14	SIMRST1	O	Reset output to an external UIM1 card	1.8 / 2.85V	
12	SIMCLK1	O	Clock output to an external UIM1 card	1.8 / 2.85V	
10	SIMIO1	I/O	Data connection with an external UIM1 card	1.8 / 2.85V	

8	SIMVCC1	O	Supply output for an external UIM1 card	1.8 / 2.85V	Power
SIM Card Interface 2					
* See note	SIMRST2	O	Reset output to an external UIM2 card	1.8 / 2.85V	
17	SIMCLK2	O	Clock output to an external UIM2 card	1.8 / 2.85V	
19	SIMIO2	I/O	Data connection with an external UIM2 card	1.8 / 2.85V	
* See note	SIMVCC2	O	Supply output for an external UIM2 card	1.8 / 2.85V	Power
Digital I/O (GPIOs)					
3	GPIO_01	I/O	General purpose I/O	1.8V	
5	GPIO_02	I/O	General purpose I/O	1.8V	
44	GPIO_03	I/O	General purpose I/O	1.8V	
46	GPIO_04	I/O	General purpose I/O	1.8V	
45	GPIO_05	I/O	General purpose I/O	1.8V	
47	GPIO_06	I/O	General purpose I/O	1.8V	
49	GPIO_07	I/O	General purpose I/O	1.8V	
51	GPIO_08	I/O	General purpose I/O	1.8V	
Power ON/OFF Reset IN/OUT					

20	W_DISABLE_N	I	Module & RF ON/OFF Control	1.8V	Active Low
* See note	SYSTEM_RESET_N	I	Reset Input	1.8V	Active Low
1.8V Voltage Regulator					
* See note	VREG_L6_1P8	O	LDO out for 1.8V	Power	

***** SIMRST2, SIMVCC2, SYSTEM_RESET_N, VREG_L6_1P8 are assigned differently to LM940 1.0 and 2.0. Please refer to the section 3 PINS ALLOCATION for more details.

All other pins have the following characteristics:

Human Body Model (HBM): ± 1000 V

Charged Device Model (CDM) JESD22-C101-C: ± 250 V

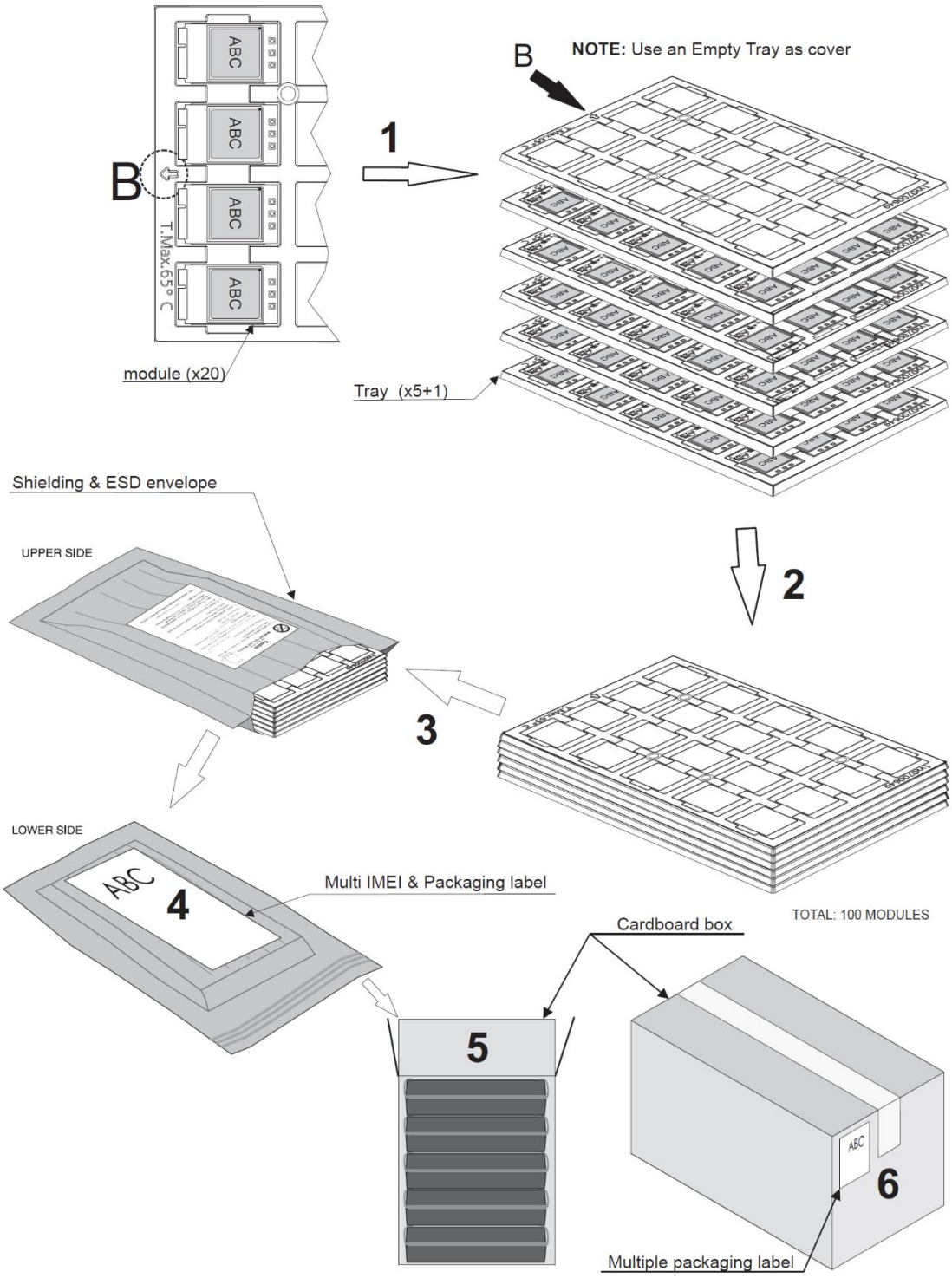
All Antenna pins up to ± 4 kV

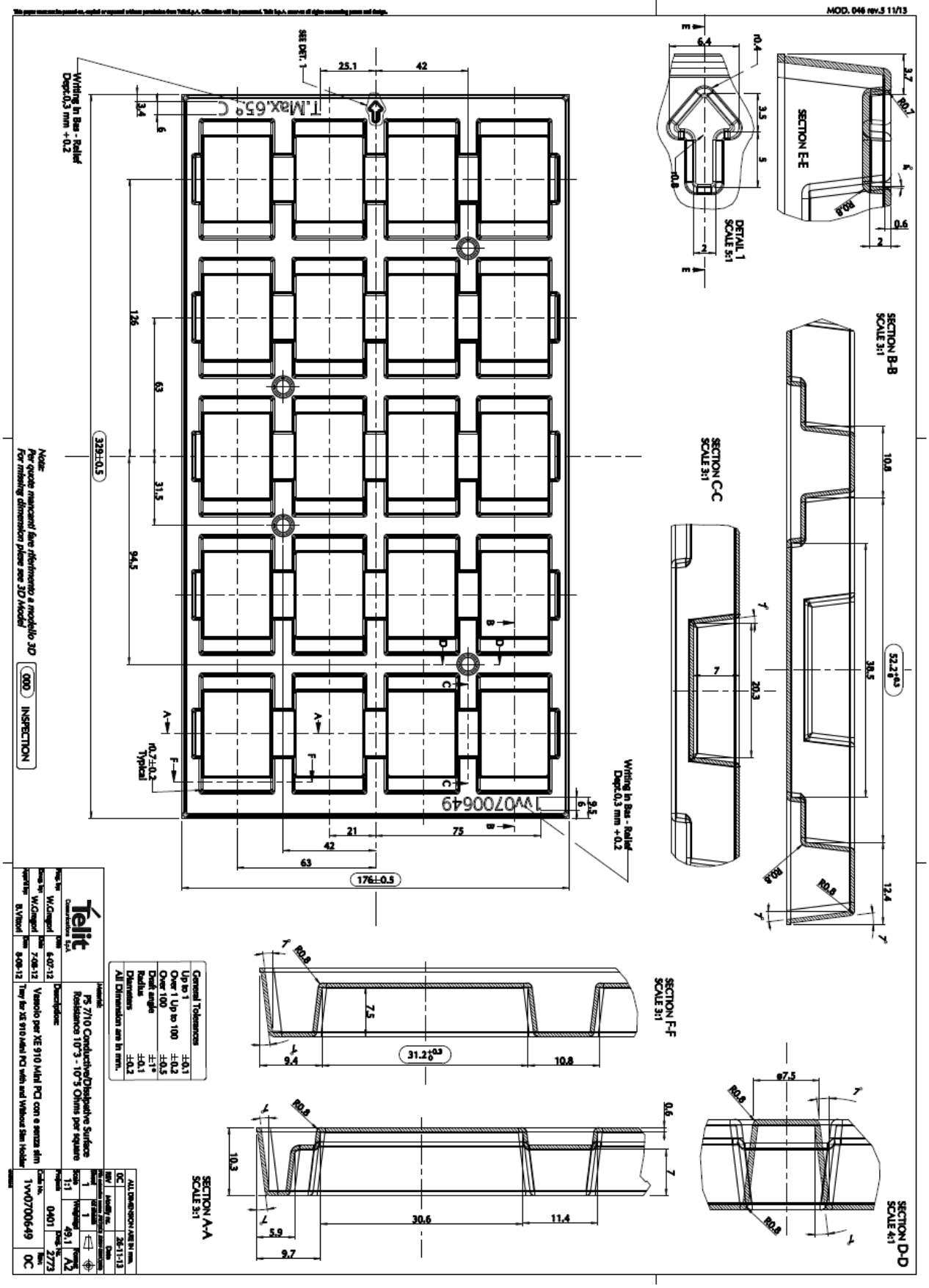
Warning – Do not touch without proper electrostatic protective equipment. The product must be handled with care, avoiding any contact with the pins because electrostatic discharge may damage the product itself.

10. PACKAGING

10.1. Tray

The LM940 modules are packaged on trays of 20 pieces each. These trays can be used in SMT processes for pick & place handling.




MOD. 046 rev.3 11/13
SEE DET. 1
25.1
42
Writing In Bas - Relief
Dept:0,3 mm +0.2
T.Max.65° C
3.4
6
126
63
31.5
94.5
329±0.5
A
F
r0.7±0.2
Typical
1VV0700649
9.5
6
21
75
42
63
176±0.5
Writing In Bas - Relief
Dept:0,3 mm +0.2
Note:
Per quote mancanti fare riferimento a modello 3D
For missing dimension please see 3D Model
000
INSPECTION
DETAIL 1
SCALE 5:1
6.4
r0.4
3.5
5
r0.8
SECTION E-E
3.7
r0.7
R0.8
0.6
2
SECTION B-B
SCALE 3:1
10.8
38.5
52.2±0.3
R0.8
R0.8
12.4
SECTION C-C
SCALE 3:1
7
20.3
SECTION F-F
SCALE 3:1
R0.8
7.5
9.4
31.2±0.3
10.8
SECTION A-A
SCALE 3:1
R0.8
0.6
10.3
7
30.6
11.4
5.9
9.7
SECTION D-D
SCALE 4:1
ø7.5
R0.9
R0.9
Telit
P5 7/10 Conductive/Dissipative Surface Resistance 10^5 - 10^6 Ohms per square
Vassoio per XE 910 Mini PCI con e senza slim Tray for XE 910 Mini PCI with and Without Slim Holder
1VV0700649
0401
2773
0C
26-11-13
W.Cinquini
6-07-12
7-08-12
8-08-12
B.Vittori
General Tolerances
Up to 1 ±0.1
Over 1 Up to 100 ±0.2
Over 100 ±0.5
Draft angle ±1°
Radius ±0.1
Dimensions ±0.2
All Dimension are in mm.

11. CONFORMITY ASSESSMENT ISSUES

11.1. Approvals

- Fully type approved confirming with RE Directive (Directive 2014/53/EU)
- CE, GCF
- FCC, IC, PTCRB
- RoHS and REACH
- Approvals for major Mobile Network Operators

11.2. Declaration of Conformity

The DoC is available here: www.telit.com/RED/

11.3. FCC certificates

The FCC Certifcate is available here: www.fcc.gov/oet/ea/fccid

11.4. IC certificates

The IC Certifcate is available here:
https://sms-sgs.ic.gc.ca/equipmentSearch/searchRadioEquipments?execution=e1s1&lang=en

11.5. FCC/IC Regulatory notices

Modification statement

Telit has not approved any changes or modifications to this device by the user. Any changes or modifications could void the user's authority to operate the equipment.

Telit n'approuve aucune modification apportée à l'appareil par l'utilisateur, quelle qu'en soit la nature. Tout changement ou modification peuvent annuler le droit d'utilisation de l'appareil par l'utilisateur.

Interference statement

This device complies with Part 15 of the FCC Rules and Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout

brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

RF exposure

This equipment complies with FCC and ISED radiation exposure limits set forth for an uncontrolled environment. The antenna should be installed and operated with minimum distance of 20 cm between the radiator and your body. Antenna gain must be below:

Cet appareil est conforme aux limites d'exposition aux rayonnements de l'ISED pour un environnement non contrôlé. L'antenne doit être installé de façon à garder une distance minimale de 20 centimètres entre la source de rayonnements et votre corps. Gain de l'antenne doit être ci-dessous:

WCDMA / LTE Antenna (except Band 30)

- Brand : HNS (HANKOOK Network Solution)
- Model Number : WE14-LF-07
- Type : Dipole Antenna

LTE Antenna for Band 30

- Brand : SAE HAN ANTENNA CO.,LTD
- Model Number : DH-23T-ANT
- Type : Dipole Antenna

Mode	Band	Antenna Gain (dBi)
LTE	FDD 1900 PCS – B2	3.5
	FDD 1800 AWS-1 – B4	3.5
	FDD 850 – B5	3.0
	FDD 2600 – B7	4.0
	FDD 700a – B12	3.0
	FDD 700c – B13	3.0
	FDD 700b – B17	3.0
	FDD 1900+ – B25	3.5
	FDD 850+ – B26	3.0
	FDD 700d – B29	3.0
	FDD 2300 WCS – B30	1.5

	FDD AWS-3 – B66	3.5
	TDD 2600 – B38	4.0
	TDD 2500 – B41	4.0
WCDMA	1900 PCS – B2	3.5
	1800 AWS-1 – B4	3.5
	850 – B5	3.0

This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

L'émetteur ne doit pas être colocalisé ni fonctionner conjointement avec à autre antenne ou autre émetteur.

FCC Class B digital device notice

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Labelling Requirements for the Host device

The host device shall be properly labelled to identify the modules within the host device. The certification label of the module shall be clearly visible at all times when installed in the host device, otherwise the host device must be labelled to display the FCC ID and ISED of

the module, preceded by the words "Contains transmitter module", or the word "Contains", or similar wording expressing the same meaning, as follows:

L'appareil hôte doit être étiqueté comme il faut pour permettre l'identification des modules qui s'y trouvent. L'étiquette de certification du module donné doit être posée sur l'appareil hôte à un endroit bien en vue en tout temps. En l'absence d'étiquette, l'appareil hôte doit porter une étiquette donnant le FCC ID et l'ISED du module, précédé des mots « Contient un module d'émission », du mot « Contient » ou d'une formulation similaire exprimant le même sens, comme suit :

LM940
Contains FCC ID: RI7LM940
Contains IC: 5131A-LM940

CAN ICES-3 (B) / NMB-3 (B)
This Class B digital apparatus complies with Canadian ICES-003.

Cet appareil numérique de classe B est conforme à la norme canadienne ICES-003.

11.6. RED Regulatory notices

RF Exposure Information (MPE)
This device has been tested and meets applicable limits for Radio Frequency (RF) exposure. To comply with the RF exposure requirements, this module must be installed in a host platform that is intended to be operated in a minimum of 20 cm separation distance to the user.

OEM/Host manufacturer responsibilities
OEM/Host manufacturers are ultimately responsible for the compliance of the Host and Module. The final product must be reassessed against all the essential requirements of the RED before it can be placed on the EU market. This includes reassessing the transmitter module for compliance with the Radio and EMF essential requirements of the RED. This module must not be incorporated into any other device or system without retesting for compliance as multi-radio and combined equipment.

Antenna Specipication

In all cases assessment of the final product must be met against the Essential requirements of the RE Directive Articles 3.1(a) and (b), safety and EMC respectively, as well as any relevant Article 3.3 requirements.

1. The following antenna was verified in the conformity testing, and for compliance the antenna shall not be modified. A separate approval is required for all other operating configurations, including different antenna configurations.
2. If any other simultaneous transmission radio is installed in the host platform together with this module, or above restrictions cannot be kept, a separate RF exposure assessment and CE equipment certification is required.

WCDMA / LTE Antenna

- Brand : HNS (HANKOOK Network Solution)
- Model Number : WE14-LF-07
- Type : Dipole Antenna

Mode	Band	Antenna Gain (dBi)
LTE	FDD 2100 – B1	3.5
	FDD 1800+ – B3	3.5
	FDD 2600 – B7	4.0
	FDD 900 – B8	3.0
	FDD 800 – B20	3.0
	FDD 700 APT – B28	3.0
	TDD 2600 – B38	4.0
	TDD 2300 – B40	4.0
WCDMA	2100 – B1	3.5
	900 – B8	3.0

Waste Electrical and Electronic Equipment (WEEE)

This symbol means that according to local laws and regulations your product and/or its battery shall be disposed of separately from household waste. When this product reaches its end of life, take it to a collection point designated by local authorities. Proper recycling of your product will protect human health and the environment.

12. SAFETY RECOMMENDATIONS

12.1. READ CAREFULLY

Be sure the use of this product is allowed in the country and in the environment required. The use of this product may be dangerous and has to be avoided in the following areas:

- Where it can interfere with other electronic devices in environments such as hospitals, airports, aircrafts, etc.
- Where there is risk of explosion such as gasoline stations, oil refineries, etc. It is the responsibility of the user to enforce the country regulation and the specific environment regulation.

Do not disassemble the product; any mark of tampering will compromise the warranty validity. We recommend following the instructions of the hardware user guides for correct wiring of the product. The product has to be supplied with a stabilized voltage source and the wiring has to be conformed to the security and fire prevention regulations. The product has to be handled with care, avoiding any contact with the pins because electrostatic discharges may damage the product itself. Same cautions have to be taken for the SIM, checking carefully the instruction for its use. Do not insert or remove the SIM when the product is in power saving mode.

The system integrator is responsible for the functioning of the final product; therefore, care has to be taken to the external components of the module, as well as any project or installation issue, because the risk of disturbing the LTE & WCDMA network or external devices or having impact on the security. Should there be any doubt, please refer to the technical documentation and the regulations in force. Every module has to be equipped with a proper antenna with specific characteristics. The antenna has to be installed with care in order to avoid any interference with other electronic devices and has to guarantee a minimum distance from the body (20 cm). In case this requirement cannot be satisfied, the system integrator has to assess the final product against the SAR regulation.

The European Community provides some Directives for the electronic equipment introduced on the market. All of the relevant information is available on the European Community website:

https://ec.europa.eu/commission/index_en

The text of the Directive 2014/35/EU regarding telecommunication equipment is available, while the applicable Directives (Low Voltage and EMC) are available at:

http://ec.europa.eu/enterprise/sectors/electrical/

13. REFERENCE TABLE OF RF BANDS CHARACTERISTICS

RF Bands Characteristics

Mode	Freq. Tx (MHz)	Freq. Rx (MHz)	Channels	Tx-Rx Offset
WCDMA 2100 – B1	1920 ~ 1980	2110 ~ 2170	Tx: 9612 ~ 9888 Rx: 10562 ~ 10838	190 MHz
WCDMA 1900 – B2	1850 ~ 1910	1930 ~ 1990	Tx: 9262 ~ 9538 Rx: 9662 ~ 9938	80 MHz
WCDMA AWS – B4	1710 ~ 1755	2110 ~ 2155	Tx: 1312 ~ 1513 Rx: 1537 ~ 1738	400 MHz
WCDMA 850 – B5	824 ~ 849	869 ~ 894	Tx: 4132 ~ 4233 Rx: 4357 ~ 4458	45 MHz
WCDMA 900 – B8	880 ~ 915	925 ~ 960	Tx: 2712 ~ 2863 Rx: 2937 ~ 3088	45 MHz
LTE 2100 – B1	1920 ~ 1980	2110 ~ 2170	Tx: 18000 ~ 18599 Rx: 0 ~ 599	190 MHz
LTE 1900 – B2	1850 ~ 1910	1930 ~ 1990	Tx: 18600 ~ 19199 Rx: 600 ~ 1199	80 MHz
LTE 1800+ – B3	1710 ~ 1785	1805 ~ 1880	Tx: 19200 ~ 19949 Rx: 1200 ~ 1949	95 MHz
LTE AWS-1 – B4	1710 ~ 1755	2110 ~ 2155	Tx: 19950 ~ 20399 Rx: 1950 ~ 2399	400 MHz
LTE 850 – B5	824 ~ 849	869 ~ 894	Tx: 20400 ~ 20649 Rx: 2400 ~ 2649	45 MHz
LTE 2600 – B7	2500 ~ 2570	2620 ~ 2690	Tx: 20750 ~ 21449 Rx: 2750 ~ 3449	120 MHz
LTE 900 – B8	880 ~ 915	925 ~ 960	Tx: 21450 ~ 21799 Rx: 3450 ~ 3799	45 MHz
LTE 700a – B12	699 ~ 716	729 ~ 746	Tx : 23010 ~ 23179 Rx : 5010 ~ 5179	30 MHz
LTE 700c – B13	777 ~ 787	746 ~ 756	Tx : 23180 ~ 23279 Rx : 5180 ~ 5279	-31 MHz

Mode	Freq. Tx (MHz)	Freq. Rx (MHz)	Channels	Tx-Rx Offset
LTE 700b – B17	704 ~ 716	734 ~ 746	Tx: 23730 ~ 23849 Rx: 5730 ~ 5849	30 MHz
LTE 800 – B20	832 ~ 862	791 ~ 821	Tx: 24150 ~ 24449 Rx: 6150 ~ 6449	-41 MHz
LTE 1900+ – B25	1850 ~ 1915	1930 ~ 1995	Tx: 26040 ~ 26689 Rx: 8040 ~ 8689	80 MHz
LTE 850+ – B26	814 ~ 849	859 ~ 894	Tx: 26690 ~ 27039 Rx: 8690 ~ 9039	45 MHz
LTE 700 APT – B28	703 ~ 748	758 ~ 803	Tx: 27210 ~ 27659 Rx: 9210 ~ 9659	55 MHz
LTE 700 d – B29	Downlink only	717 ~ 728	Rx: 9660 ~ 9769	–
LTE 2300 WCS – B30	Downlink only	2350 ~ 2360	Rx: 9770 ~ 9869	–
LTE AWS-3 – B66	1710 ~ 1780	2110 ~ 2200	Tx: 131972 ~ 132671 Rx: 66436 ~ 67335	400 MHz
LTE TDD 2600 – B38	2570 ~ 2620	2570 ~ 2620	Tx: 37750 ~ 38249 Rx: 37750 ~ 38249	0 MHz
LTE TDD 2300 – B40	2300 ~ 2400	2300 ~ 2400	Tx: 38650 ~ 39649 Rx: 38650 ~ 39649	0 MHz
LTE TDD 2500 – B41	2496 ~ 2690	2496 ~ 2690	Tx: 39650 ~ 41589 Rx: 39650 ~ 41589	0 MHz

NOTE – The channel numbers that designate carrier frequencies so close to the operating band edges that the carrier extends beyond the operating band edge shall not be used. This implies that the first 7, 15, 25, 50, 75 and 100 channel numbers at the lower operating band edge and the last 6, 14, 24, 49, 74 and 99 channel numbers at the upper operating band edge shall not be used for channel bandwidths of 1.4, 3, 5, 10, 15 and 20 MHz respectively.

NOTE – For more information on bandwidth support, refer to 3GPP TS 36.521-1 V15.0.0, Table 5.4.2.1-1.

14. ACRONYMS

TTSC	Telit Technical Support Centre
USB	Universal Serial Bus
HS	High Speed
DTE	Data Terminal Equipment
UMTS	Universal Mobile Telecommunication System
WCDMA	Wideband Code Division Multiple Access
HSDPA	High Speed Downlink Packet Access
HSUPA	High Speed Uplink Packet Access
UART	Universal Asynchronous Receiver Transmitter
HSIC	High Speed Inter Chip
SIM	Subscriber Identification Module
SPI	Serial Peripheral Interface
ADC	Analog – Digital Converter
DAC	Digital – Analog Converter
I/O	Input Output
GPIO	General Purpose Input Output
CMOS	Complementary Metal – Oxide Semiconductor
MOSI	Master Output – Slave Input
MISO	Master Input – Slave Output
CLK	Clock
MRDY	Master Ready

SRDY	Slave Ready
CS	Chip Select
RTC	Real Time Clock
PCB	Printed Circuit Board
ESR	Equivalent Resistance
VSWR	Voltage Standing Wave Radio
VNA	Vector Network Analyzer
FDD	Frequency division duplex
I2C	Inter-integrated circuit
LTE	Long term evolution
SOC	System-on-Chip

15. DOCUMENT HISTORY

Revision	Date	Changes
0	2017-01-17	First Draft
1	2017-06-23	Changed document form
2	2017-07-19	Updated 7 RF section Updated 11.5 RF exposure
3	2017-08-17	Updated 11.1 Approvals Updated 11.5 RF exposure Added 11.6 RED Regulatory Notices Updated 12 Safety Recommendations
4	2017-11-01	Added 2.8 GNSS Receiver Specifications Updated 2.2.1 RF bands per Regional Variant Updated 8.3 Drawing Updated 13 RF bands Characteristics
5	2018-02-22	Updated 13 RF bands Characteristics Added 6.3 Added Warning
6	2018-04-25	Added 6.5.1 Warning Deleted Audio Section Dected WWAN_LED_N, WAKE_N Section
7	2018-12-06	Updated 2 General product description
8	2019-03-15	6 Digital Section Changed description about setting GPIO as specific function. Updated 6.2 Power ON Updated 6.3 Power Off Fast Shutdown Trigger: Low Edge Trigger Updated 6.4 Reset Added 6.5 Dying Gasp Dying Gasp Trigger: Low Edge Trigger Added and updated 6.6.4.2 WAN_LED_N Added 6.6.5.3 Dedicated I/O According to the merging LM940 1.0 and LM940 Design guide, following sections are changed.

		Applicability Table, Section 3, Section 6.6.2, Section 9.3
9	2019-05-28	Deleted some sentence in 2.1 Overview Deleted some words in 2.4 Main features Updated 6.3.2 Fast Shutdown Timing
10	2019-05-28	Editorial changes
11	2019-06-14	Moisture Sensitivity Level paragraph added
12	2019-07-18	Band and CA combinations tables updated
13	2020-01-21	Moisture Sensitivity Level corrected
14	2020-02-05	Moisture Sensitivity Level Declaration removed
15	2020-05-11	CA combo table header corrected

SUPPORT INQUIRIES

Link to **www.telit.com** and contact our technical support team for any questions related to technical issues.

www.telit.com

Telit Communications S.p.A.
Via Stazione di Prosecco, 5/B
I-34010 Sgonico (Trieste), Italy

Telit IoT Platforms LLC
5300 Broken Sound Blvd, Suite 150
Boca Raton, FL 33487, USA

Telit Wireless Solutions Inc.
3131 RDU Center Drive, Suite 135
Morrisville, NC 27560, USA

Telit Wireless Solutions Co., Ltd.
8th Fl., Shinyoung Securities Bld.
6, Gukjegeumyung-ro8-gil, Yeongdeungpo-gu
Seoul, 150-884, Korea

Telit Wireless Solutions Ltd.
10 Habarzel St.
Tel Aviv 69710, Israel

Telit Wireless Solutions
Technologia e Servicos Ltda
Avenida Paulista, 1776, Room 10.C
01310-921 São Paulo, Brazil

Mod.0818 2017-01 Rev.0

[01.2017]